APPLIED MATERIALS STYLE GUIDE

eleveneightyfivedesign

APPLIED MATERIALS LITERATURE SURVEY

eleveneightyfivedesign

MARKETING LITERATURE SURVEY GOALS

The purpose of this survey is to gather feedback from regional and product marcom managers to help us develop a long-range marketing literature strategy that not only effectively addresses Applied Material's needs for marketing literature, but also to help Applied Materials establish a better relationship with their customers.

PRODUCT AND REGIONAL MARCOM SURVEY RESULTS

7 responses to 31 emailed surveys

- Needs to reflect Brand image
- Convey visionary, innovative and accessible image
- Must be a flexible or modular system
- Must look like it all comes from the same company
- Templates (clear and explicit with examples)
- Templates must be accessible
- Standard sizes, everything to fit in standard envelopes/file cabinets
- System needs to work consistently—from AR to datasheets to Powerpoint presentations

WORLDWIDE SURVEY RESULTS

10% Total Response
73% From Marketing and Sales
80% From North America and Europe

When you think of Applied Materials, is there one image that comes to mind?:

Similar results to McCann-Erickson survey

- Leaders
- Big and powerful—but also aggressive, 800 lb gorilla, inflexible, stuffy
- Divisions market themselves autonomously

Collateral pieces most used:

90.48% (57) Powerpoint Presentations
79.37% (50) Presentation Templates
69.84% (44) Datasheets
68.25% (43) Corporate Backgrounder
63.49% (40) Annual Report
63.49% (40) Product Portfolio
60.32% (38) Brochures
39.68% (25) Newsletters
39.68% (25) Graphic Panels
38.10% (24) Product Briefs
36.51% (23) Invitations
31.75% (20) Corporate Folder
31.75% (20) Customer Stories
30.16% (19) White Papers
28.57% (18) Posters
23.81% (15) Division Folder
14.29% (9) Service Briefs
14.29% (9) Other

Which do you find most effective and why?

- **Powerpoint presentations**—since they "can be kept current and are easily tailored to specific information and audiences"
- **Datasheets**—"data is critical and customers are too savvy to make decisions on generic material"
- **Product Overview**—"as it gives me the information on all of Applied Materials products without going into too much detail"
- **Annual Report and Corporate Backgrounder**—"comprehensive company information usable by a wide audience with limited detailed technical knowledge"

Does the current literature have the appropriate content?

- 86% yes, but...
- Would like to see more proofs/facts, success stories, and benefits, not just features
- Information/data is hard to get
- Information/data is out-of-date
- Inconsistencies in content between and within divisions, "some are complete to include process specs; hardware specs; facilities requirements; fab layout/dimensions. Not the case with other divisions".

Is there enough technical information?

- 81% yes, but...
- Too technical, need stronger and consistent messaging
- Not enough information on services
- Out-of-date
- Can't get a hold of data/information

APPLIED MATERIALS SURVEY

Is the tone, as far as color, imaging and fonts, representative of Applied Materials and your division?

- Like Applied Materials blue (PMS 5405)
- Would like to see lighter palette (brighter future)
- Would like accessible templates and graphics
- Would like Web access to all literature materials and assets
- Too conservative
- Inconsistent, internal as well as external "I do not like to see inconsistent presentation templates (fonts, colors, etc.). Even within a PBG/division I see a number of various formats, fonts, etc. that give inconsistent branding."
- Brand is not leveraged consistently or at all

Does the literature need product photography?

- 94% yes
- Need quick access to image library
- Out-of-date
- Expensive and timely to keep current
- Need both technical images and beauty images
- Need library of images for service, software and results of what tools can do

Which marketing piece, if any, do customers request the most?

- Specifications, datasheets (20%)
- Brochures (14%)
- Powerpoint presentations (5%)
- White papers (5%)
- Don't know (7%)

Does the design/layout of the marketing literature help reinforce the key messages?

- 75% yes
- Need consistent and better messaging
- Messaging does not work when integrating (each PBG has its own)
- Need different levels for messaging (templates)
- PBG name overshadows Applied Materials brand

Other recommendations or comments

- Flexibility
- Consistency and synergy "CONSISTENCY; CONSISTENCY; CONSISTENCY. Lack of synergy between product business groups is embarrassing at times. I shouldn't have to explain that to a customer. I need to stay proactive and sell our strengths, not explain our weaknesses."
- Ability to tailor literature to customer needs
- Electronic access to templates, guidelines and collateral assets
- Customer base and general public able to access literature (Web, PDFs)
- Access to corporate as well as technical literature
- Afraid of impact of a new style guide
- An upbeat and lively look and feel

BUILDING BLOCKS FOR CHIP MANUFACTURING

elevenei**ghty**five**design**

The Creative:

Corporate Brochure

Corporate Folder Cover

CPI Datasheet

Product Brochure Covers

The Concept: **Building Blocks**

The grid used throughout the collateral reinforces the building block theme. Each square of the grid can be associated with a division or part of Applied Materials, when together these building blocks become the foundation or guidelines for chip manufacturing around the world. The grid has 2 roles it can be used as a design element and it is the actual grid upon which all elements in the pieces should use as a guide for placement. It is a flexible system, and can be used openly with a variety of designs as long as it falls within the delegated grid.

Core Values:

Applied Materials is the largest supplier of products and services to the global semiconductor industry and is one of the world's leading information infrastructure providers. Applied Materials enables Information for Everyone by helping semiconductor manufacturers produce more powerful, portable and affordable chips.

Target Audience:

Varies on the collateral pieces. Materials generally target the CIO, CFO or the technology decision makers within a chip making organization.

Primary Objective:

To create a recognizable, unique brand identity that is consistent in messaging and design.
The Look and Feel needs to express Applied Materials personality and position in a global marketplace.

Survey Results:

(a brief summary)

- To become more **approachable**
- **Less autonomy** among divisions
- Create **brand recognition**
- Continue to project **leadership** image
- **Less conservative** image
- Moving towards a **brighter future**

Typography:

Frutiger Light
Frutiger Roman
Frutiger Italic
Frutiger Condensed
Frutiger Bold Condensed
Frutiger Bold
Frutiger Bold Italic
Frutiger Black

Caslon Regular
Caslon Semibold
Caslon Italic
Caslon Bold Italic
Caslon Bold

Color Palette:

Grid System:

Division titles will always be placed vertically

Logo is always placed on the bottom

All content should use this grid as a guide for placement

Black bar takes up the height of 2 squares of the grid. For brochures, this should be filled in black, other pieces such as datasheets are allowed to define the space with a line treatment as shown below

All content should use this grid as a guide for placement

Treatment of the Photography:

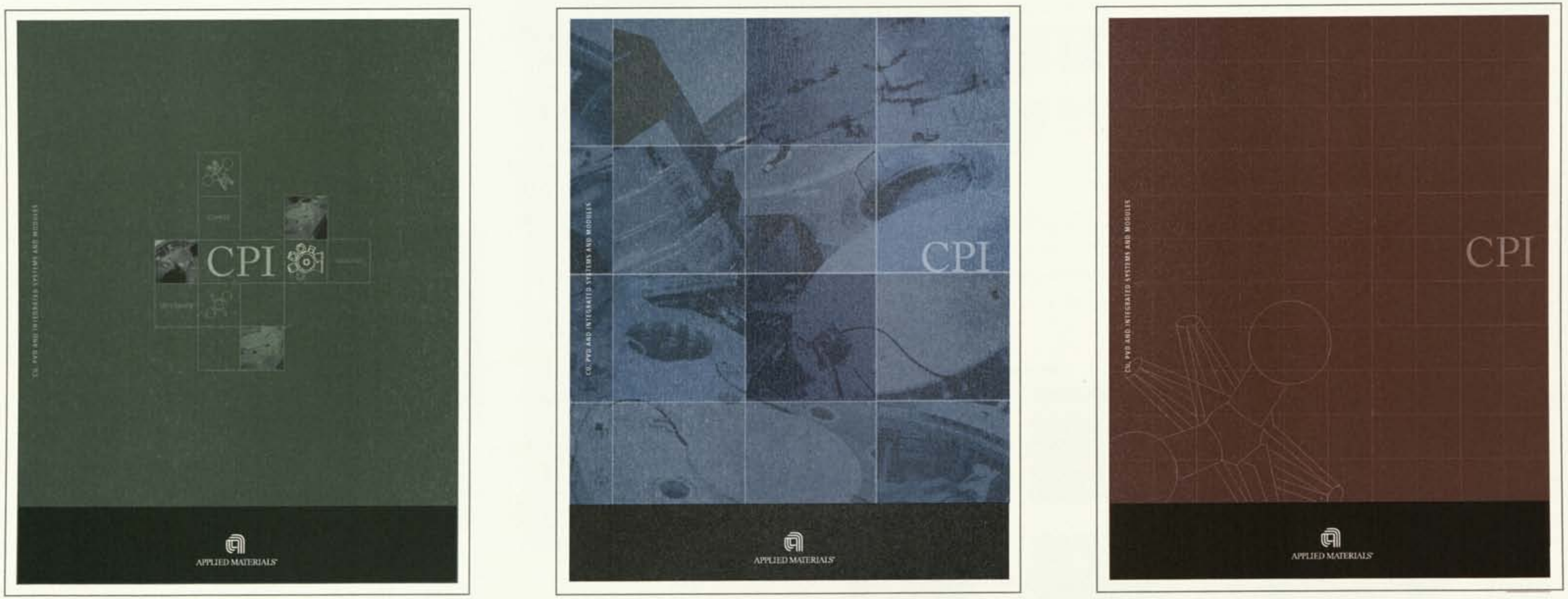
Duotone, greyscale as well as 4 color images are used throughout the collateral. Products photos are frequently tightly cropped shots. Higher end pieces will utilize 4 color images more frequently, while other pieces will utilize the duotone and greyscale images.





Emboss rectangle

Brochure Cover



CPI Cover Variations

CPS Cover Variations

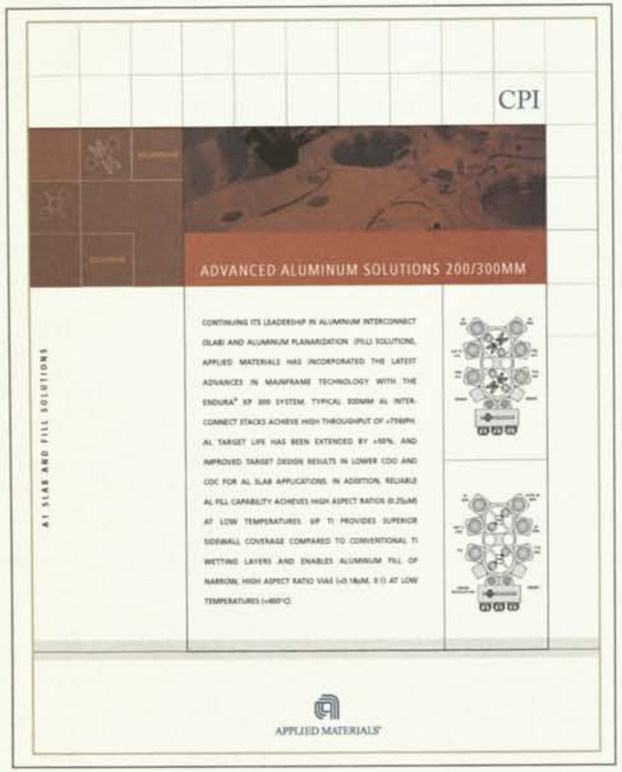
Building Tomorrow's Technology

Looking Ahead.

Building Tomorrow's Technology

Looking Ahead.

Brochure Inside Variations



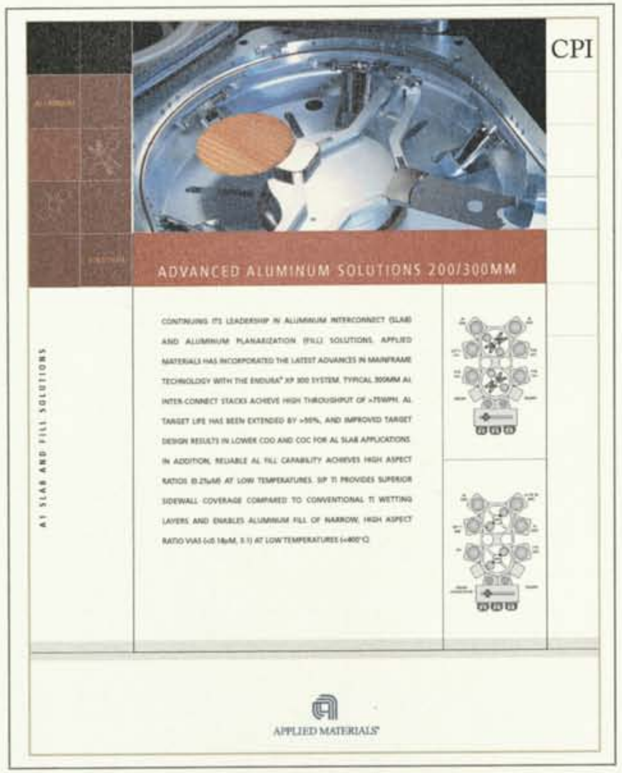
CPI

ADVANCED ALUMINUM SOLUTIONS 200/300MM

AI SLAB AND FILL SOLUTIONS

CONTINUING ITS LEADERSHIP IN ALUMINUM INTERCONNECT (SLAB) AND ALUMINUM PLANARIZATION (FILL) SOLUTIONS, APPLIED MATERIALS HAS INCORPORATED THE LATEST ADVANCES IN MAINFRAME TECHNOLOGY WITH THE ENDURA® XP 300 SYSTEM. TYPICAL 300MM AL INTERCONNECT STACKS ACHIEVE HIGH THROUGHPUT OF >75WPH. AL TARGET LIFE HAS BEEN EXTENDED BY >50%, AND IMPROVED TARGET DESIGN RESULTS IN LOWER COO AND COC FOR AL SLAB APPLICATIONS. IN ADDITION, RELIABLE AL FILL CAPABILITY ACHIEVES HIGH ASPECT RATIOS (0.25μM) AT LOW TEMPERATURES. SIP TI PROVIDES SUPERIOR SIDEWALL COVERAGE COMPARED TO CONVENTIONAL TI WETTING LAYERS AND ENABLES ALUMINUM FILL OF NARROW, HIGH ASPECT RATIO VIAS (<0.18μM, 3:1) AT LOW TEMPERATURES (<400°C).

APPLIED MATERIALS®



CPI

ADVANCED ALUMINUM SOLUTIONS 200/300MM

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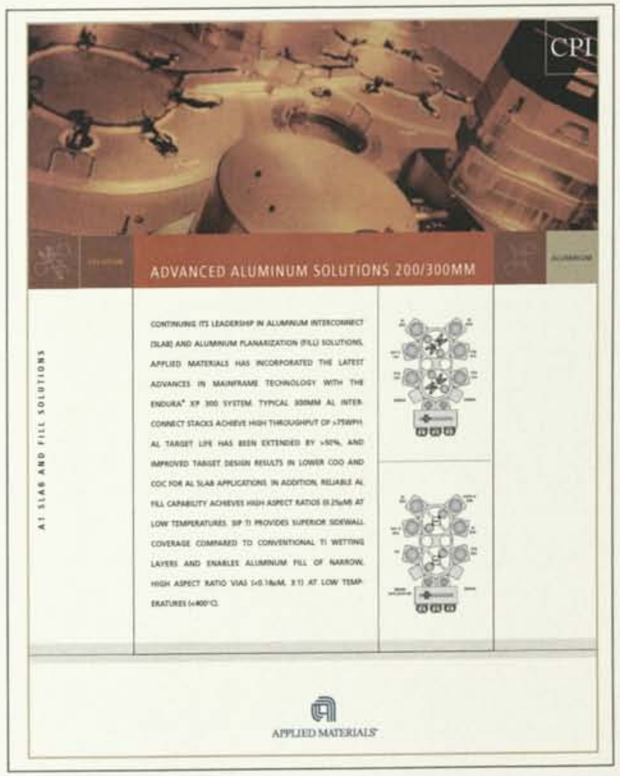
APPLIED MATERIALS®



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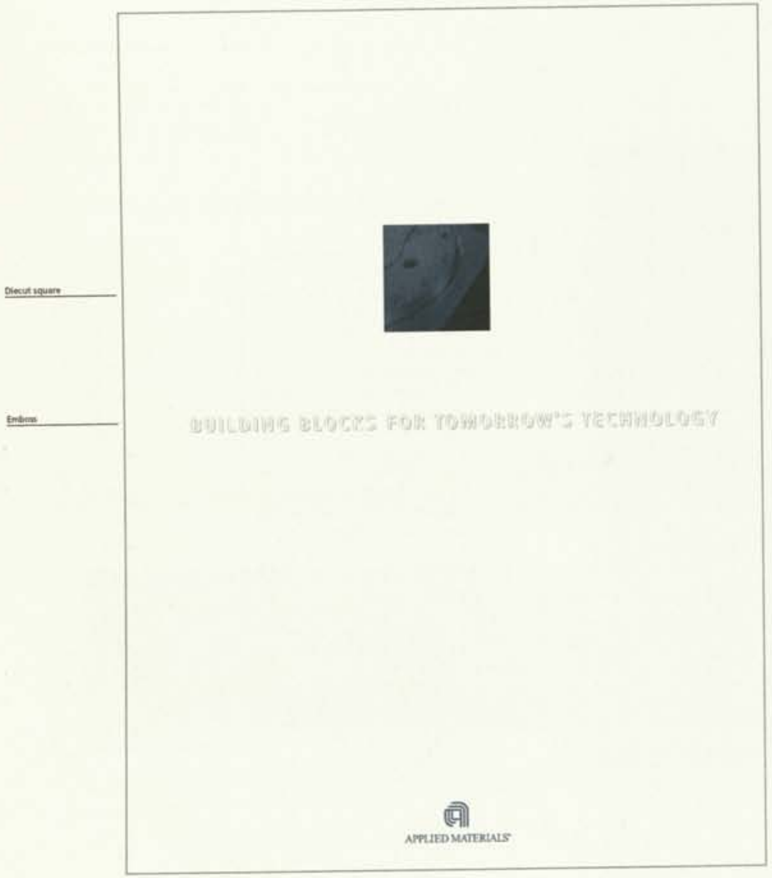
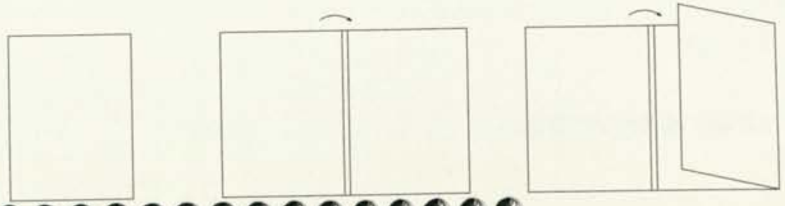
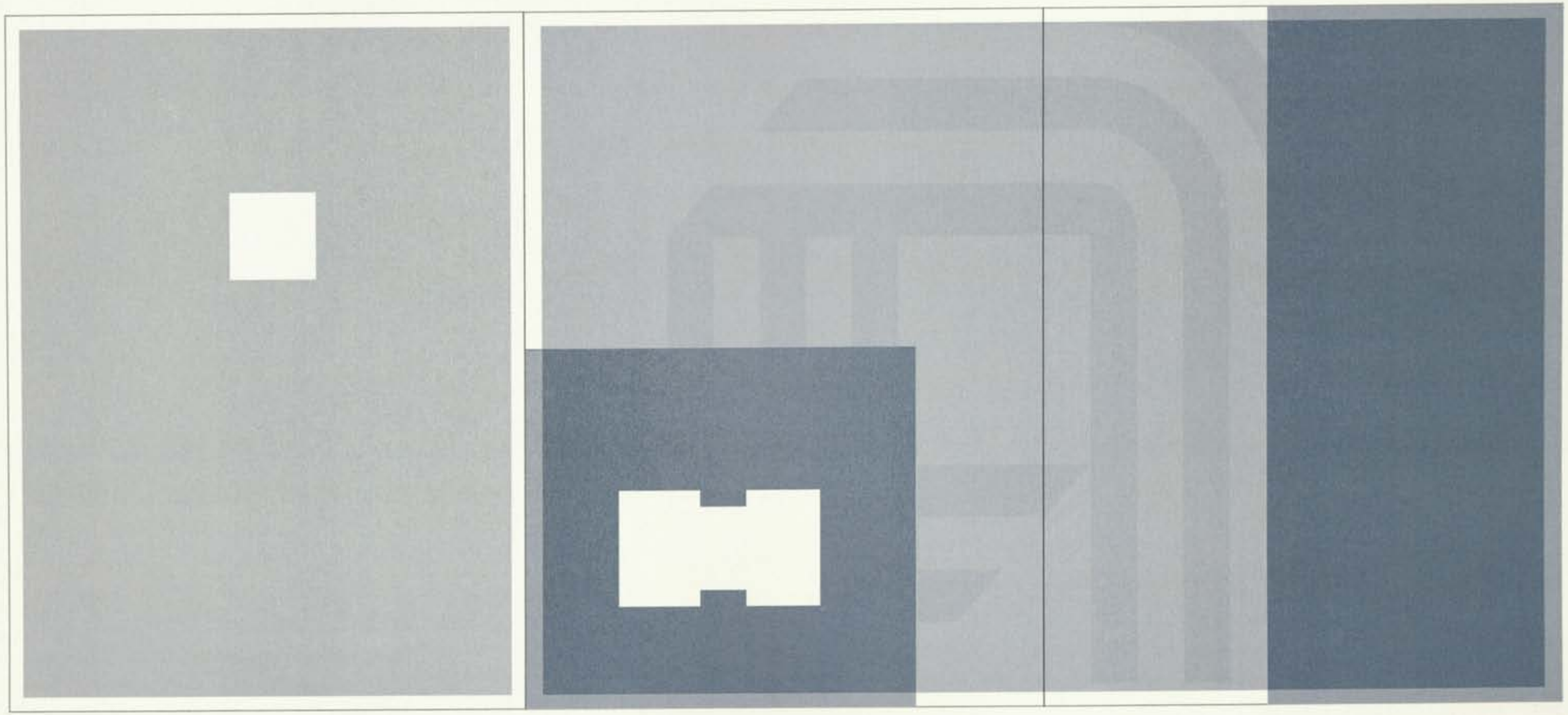
Datasheet Variations



Folder Cover

Folder Inside Front Cover





Folder Inside

ELEMENTS—THE BASICS

Typography:

ITC Franklin Gothic Book
ITC Franklin Gothic Book Oblique
ITC Franklin Gothic Demi
ITC Franklin Gothic Demi Oblique
ITC Franklin Gothic Heavy
ITC Franklin Gothic Heavy Oblique

Minion Regular
MINION REGULAR SMALL CAPS
Minion Regular Italic
Minion Semibold
MINION SEMIBOLD SMALL CAPS
Minion Semibold Italic
Minion Black

Color Palette:

AMAT					
PMS 5405	PMS 1795	PMS 124	W. Gray 5	PMS 424	PMS 447
Metallic			Gold 871	Copper 876	Silver 877

CPI	DSM	ECH	CMP	TCG	PCI
PMS 5473	PMS 301	PMS 491	PMS 575	PMS 470	PMS 202
FPS	**CPS**	**PDC**	**MSK**	**FPD**	
PMS 5125	PMS 668	PMS 5265	PMS 5545	PMS 7469	

Division Identifiers, Acronyms and Icons:

Applied Materials - Global
CPI **CPI - Metal Deposition**
DSM **DSM - Insulation Deposition**
ECH **Etch - Removal from surface**
CMP **CMP - Polishing Action**
TCG **TCG - Implantation**

MSK **Mask - Isolating**
PCI **PCI - Dopant Implantation**
FPS **FPS - Product on Conveyer Belt**
CPS **CPS - Customer Representation**
PDC **PDC - Diagnostic**
FPD **FPD - Flat Panel Display**

The Grid System:

The basic Grid System is dividing the page into 10x12 squares which is used for positioning of elements within the page. There is also a 8 column grid, for text that fits into the Square grid system, any combination of the column grid is acceptable except a one column usage.

Consistent Element

The Title:
For Brochures using the same type and style

The Vertical Bar
At .425" and at 100% of the devisions color

The Logo
Always reversed out and same location

Consistent Element

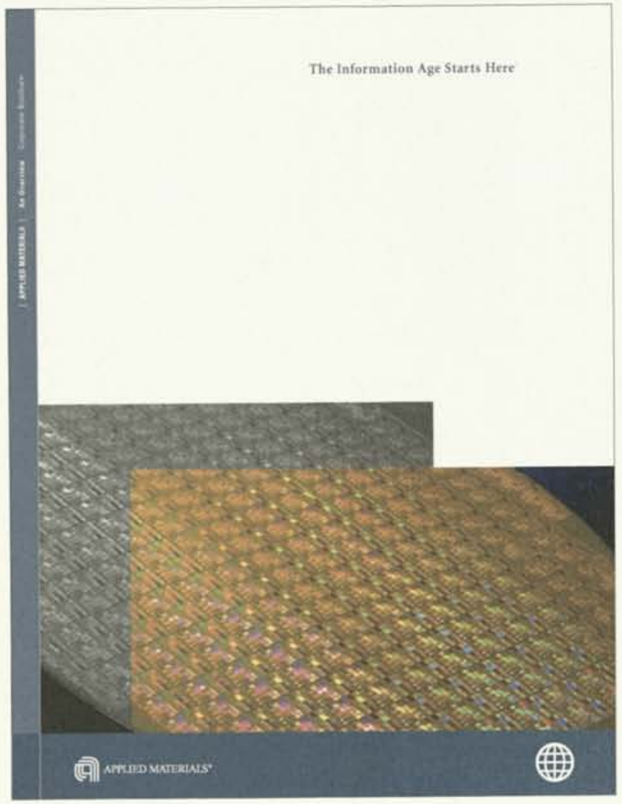
The Division Acronym
Always at the same location, but the treatment could vary

The Division Icon
Always at the same location, reversed out

The Horizantal Bar
At .917" height and at 85% of the devisions color

Treatment of the Photography:

Tightly cropped Color, Black and White and duotone photography will be used throughout the system. To show the product in full, color imagery should be used.



APPLIED MATERIALS | An Overview | Corporate Brochure

The Information Age Starts Here

APPLIED MATERIALS®

Corporate Brochure Cover

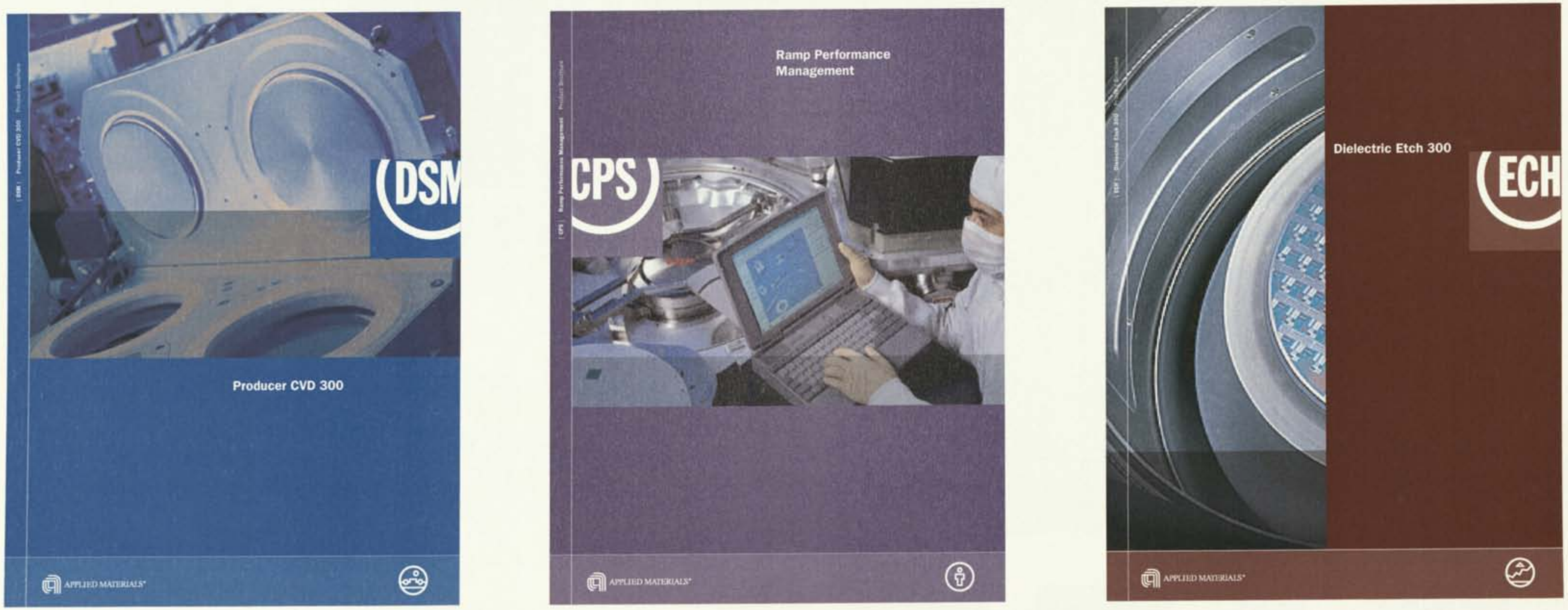
AT APPLIED MATERIALS WE MAKE
THE SYSTEMS THAT MAKE THE
CHIPS THAT MAKE THE PRODUCTS
THAT CHANGE THE WORLD

In 1967 apricot orchards still covered much of Northern California's Santa Clara Valley. Alongside the orchards, a young semiconductor industry was quietly spreading its roots and beginning to bear an entirely new kind of fruit tiny integrated circuits, or chips, that would help send men to the moon and a decade later power the first personal computers. Only a few pioneers could then imagine their extraordinary potential. Applied Materials was one of these pioneers. The Company was founded by Mike McNeilly to provide the equipment that these semiconductor companies required to make their revolutionary chips.

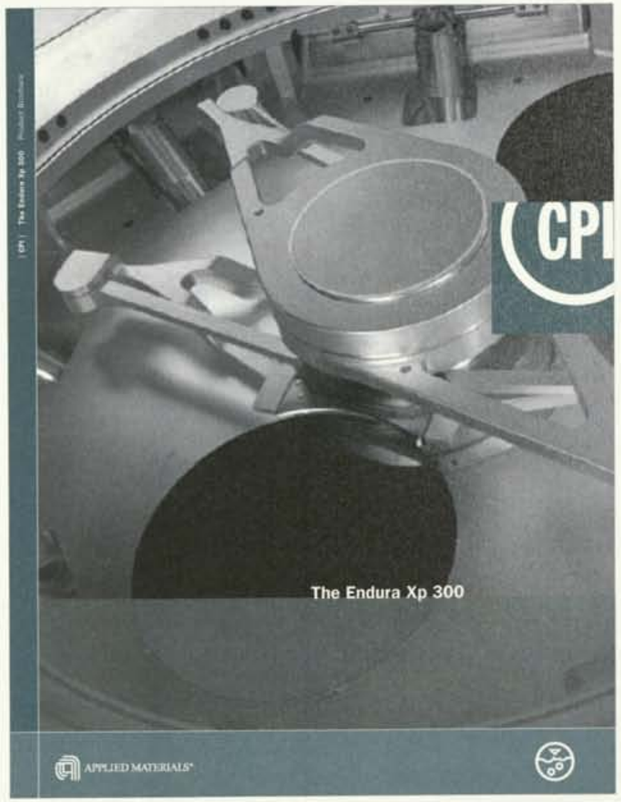
The semiconductor industry soon proved so fertile it not only transformed the sleepy Santa Clara Valley into ŒSilicon Valley, launching the Information Age, but spread far and wide across the globe. Driven first by the electronics industry, then rocketed upwards by the advent of personal computers, the chip industry exploded from a $2 billion dollar industry in the late 1960s to over $180 billion today. As semiconductor fabrication boomed, Applied Materials also blossomed. Growing from a single-product business with $100,000 in first-year sales, and expanding rapidly under the dynamic leadership of CEO Jim Morgan (who joined the company in 1976), we have become the world,s largest supplier of semiconductor manufacturing equipment.

Every chip. Every day. Everywhere.

Corporate Brochure Inside Cover



Product Brochure Cover Options

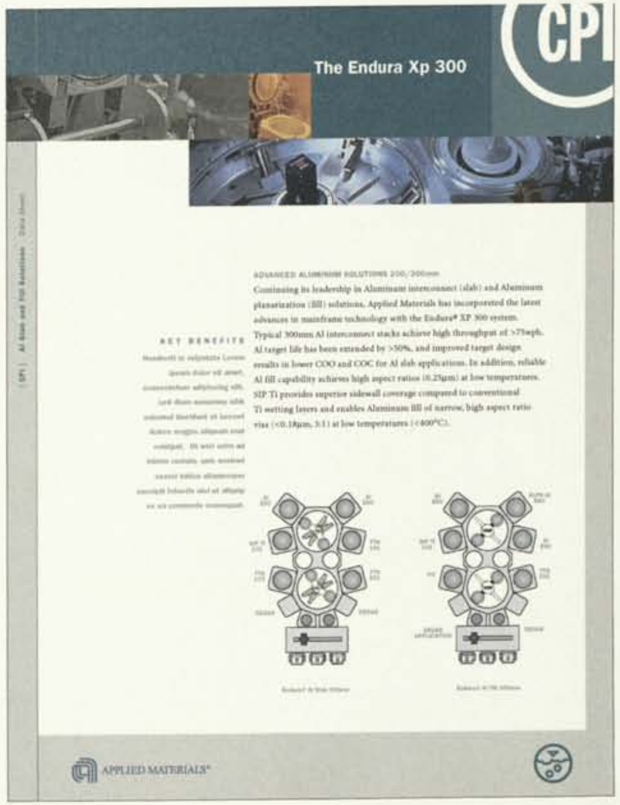


CPI

The Endura Xp 300

APPLIED MATERIALS®

CPI Product Brochure



The Endura Xp 300

CPI

ADVANCED ALUMINUM SOLUTIONS 200/300mm

Continuing its leadership in Aluminum interconnect (slab) and Aluminum planarization (fill) solutions, Applied Materials has incorporated the latest advances in mainframe technology with the Endura® XP 300 system. Typical 300mm Al interconnect stacks achieve high throughput of >75wph. Al target life has been extended by >50%, and improved target design results in lower COO and COC for Al slab applications. In addition, reliable Al fill capability achieves high aspect ratios (0.25µm) at low temperatures. SIP Ti provides superior sidewall coverage compared to conventional Ti wetting layers and enables Aluminum fill of narrow, high aspect ratio vias (<0.18µm, 5:1) at low temperatures (<400°C).

KEY BENEFITS

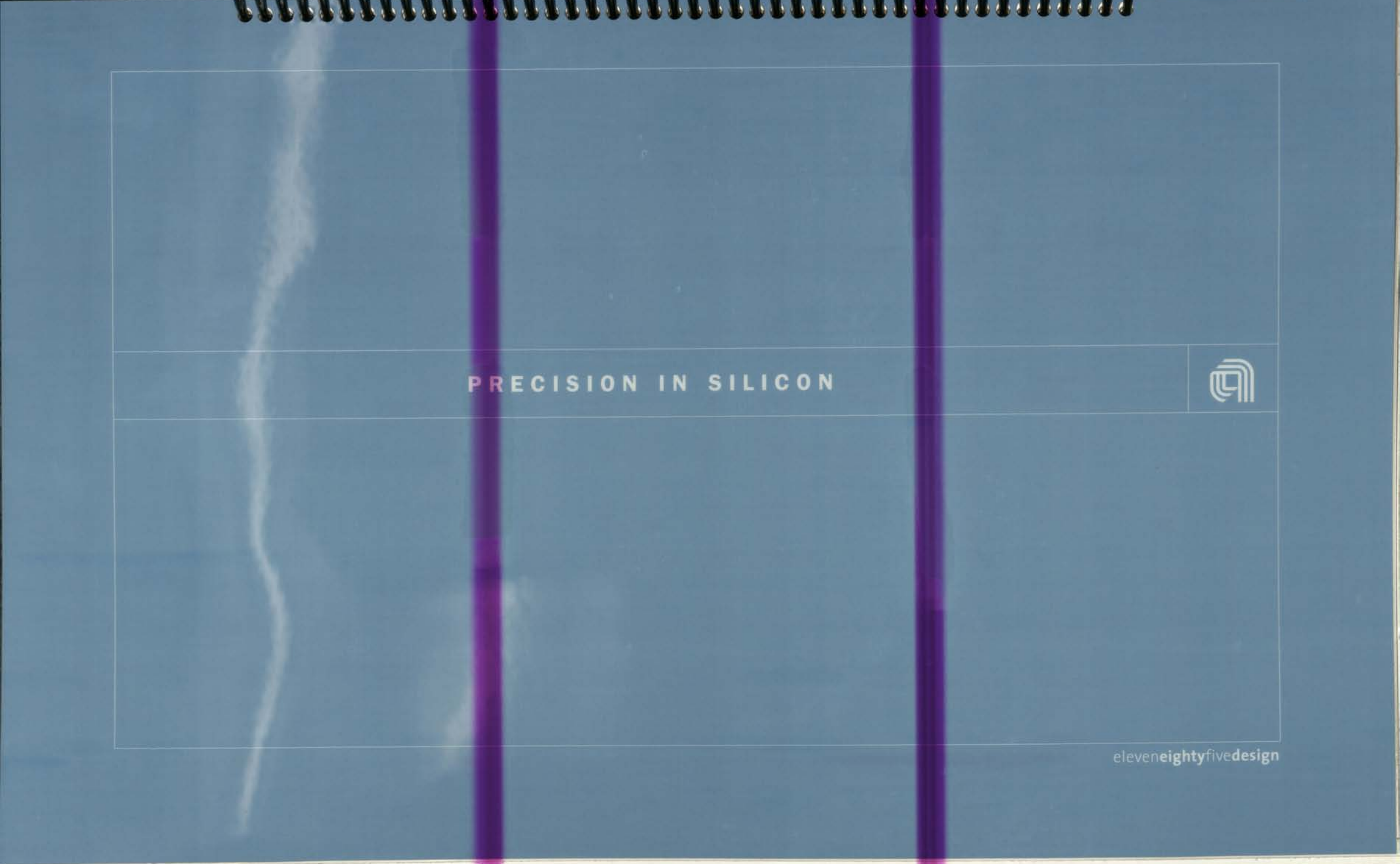
[illegible]

APPLIED MATERIALS®

CPI Product Data Sheet


DSM
information for everyone
APPLIED MATERIALS®


DSM
APPLIED MATERIALS®



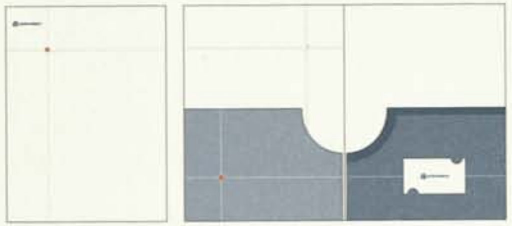
PRECISION IN SILICON

eleven**eighty**five**design**

PRECISION IN SILICON

The Creative:

Corporate Brochure



Corporate Folder

Product Brochure Covers

CPI Datasheet

The Concept: Precision in Silicon

Applied Materials creates the basic equipment for manufacturing chips. Sand is the basic element for creating silicon. The art of converting a silicon wafer into a chip requires the utmost precision. This concept focuses on this exacting piece of this process. The rule and circle graphic ("precision rule graphic") represent the precision concept, while the photographic icons of images drawn in the sand reiterate that the foundation of silicon.

Core Values:

Applied Materials is the largest supplier of products and services to the global semiconductor industry and is one of the world's leading information infrastructure providers. Applied Materials enables Information for Everyone by helping semiconductor manufacturers produce more powerful, portable and affordable chips.

Target Audience:

Varies on the collateral pieces. Materials generally target the CIO, CFO or the technology decision makers within a chip making organization.

Primary Objective:

To create a recognizable, unique brand identity that is consistent in messaging and design. The Look and Feel needs to express AMAT's personality and position in a global marketplace.

Survey Results:

(a brief summary)

- To become more **approachable**
- **Less autonomy** among divisions
- Create **brand recognition**
- Continue to project **leadership** image
- **Humanizing** technical aspects of literature
- **Less conservative** image
- Moving towards a **brighter future**

APPLIED MATERIALS STYLE GUIDE

PRECISION IN SILICON

Typography:

Meta Plus Normal
Meta Plus Normal Italic
Meta Plus Medium
Meta Plus Medium Italic
Meta Plus Bold
Meta Plus Black

Caslon 540 Regular
Caslon 540 Italic
CASLON 540 ROMAN SMALL CAPS & FIGURES
Caslon 540 Italic Old Style Figures

Color Palette:

PMS 5405	PMS 5265	PMS 5825	PMS 718	PMS 201	PMS 130	PMS 293	PMS 2617	PMS 370	PMS 1655	PMS 227	PMS 116
PMS 5425	PMS 5275	PMS 5845	PMS 716	PMS 1797	PMS 124	PMS 279	PMS Violet	PMS 383	PMS 1585	PMS 226	PMS 109

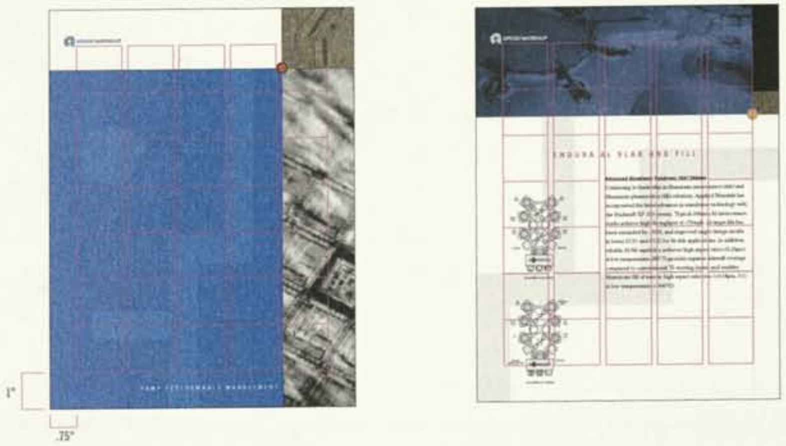
Division Identifiers, Acronyms and Icons:

Applied Materials - Precision
CPI - Metal Deposition
DSM - Insulation Deposition
Etch - Removal from surface
CMP - Polishing Action
TCG - Transistor

Mask - Isolating
PCI - Dopant Implantation
FPS - Product on Conveyer Belt
CPS - Customer Representation
PDC - Diagnostic
FPD - Flat Panel Display

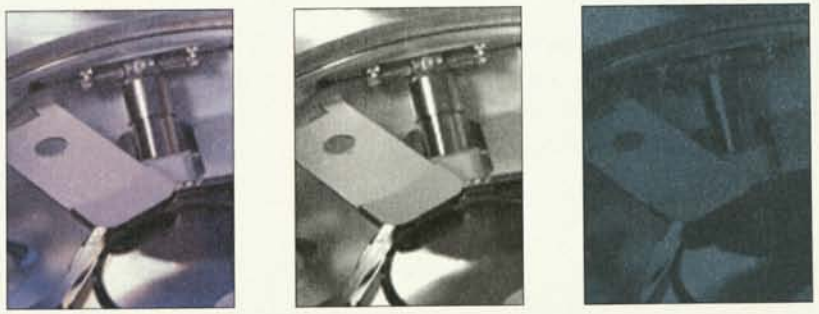
The Grid System:

This 5-column grid was designed for flexibility. The addtion of a 14 row vertical grid, helps to maintain a consistent look throughout the system. The constant elements are called out below with their specific rules. Constant elements include: logo, precision rule graphic, photo icons, and graphic icons.

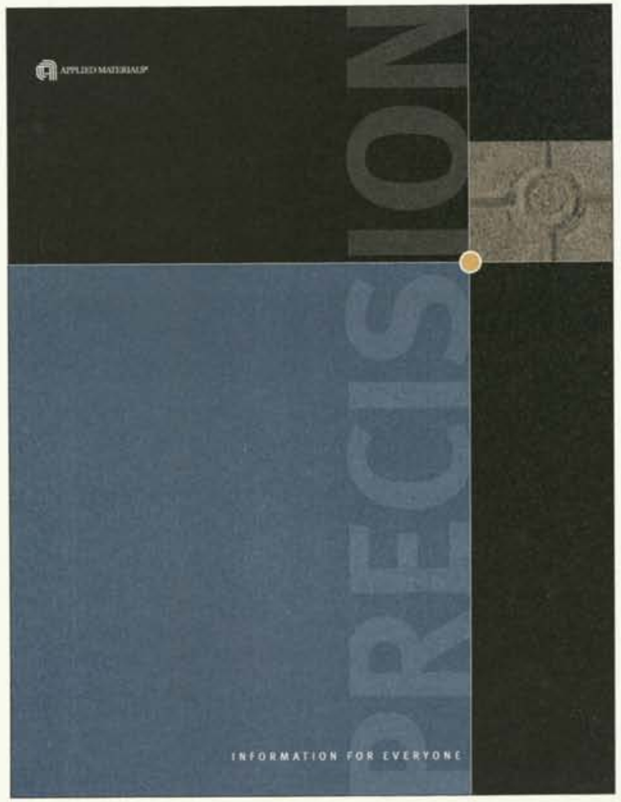


Treatment of the Photography:

The Photography is always tightly cropped, to create a more dramatic feel to the piece. It may be used as full color, black and white, or a highly saturated duotone



PRECISION IN SILICON



Corporate Brochure cover

IT STARTS WITH OUR PRODUCTS. Over 30 years of non-stop innovation and commercialization have made us the leading supplier of advanced semiconductor manufacturing equipment. **IT STARTS WITH OUR PEOPLE.** Our employees are the foundation of Applied Materials' success. Their tremendous talent allows us to deliver increasingly productive equipment to our customers, enabling their business success. **IT STARTS WITH OUR VISION.** Only a global company that's been built to change is destined to last. We have created a collaborative and decisive organization with the capabilities we need to thrive in the 21st century.

AT APPLIED MATERIALS WE MAKE THE SYSTEMS THAT MAKE THE CHIPS THAT MAKE THE PRODUCTS THAT CHANGE THE WORLD

In 1967 apricot orchards still covered much of Northern California's Santa Clara Valley. Alongside the orchards, a young semiconductor industry was quietly spreading its roots and beginning to bear an entirely new kind of fruit—tiny integrated circuits, or chips, that would help send men to the moon and a decade later power the first personal computers. Only a few pioneers could then imagine their extraordinary potential. Applied Materials was one of these pioneers. The Company was founded by Mike McNeilly to provide the equipment that these semiconductor companies required to make their revolutionary chips.

The semiconductor industry soon proved so fertile it not only transformed the sleepy Santa Clara Valley into "Silicon Valley," launching the Information Age, but spread far and wide across the globe. Driven first by the electronics industry, then rocketed upwards by the advent of personal computers, the chip industry exploded from a $2 billion dollar industry in the late 1960s to over $180 billion today. As semiconductor fabrication boomed, Applied Materials also blossomed. Growing from a single-product business with $100,000 in first-year sales, and expanding rapidly under the dynamic leadership of CEO Jim Morgan (who joined the company in 1976), we have become the world's largest supplier of semiconductor manufacturing equipment.

Every chip. Every day. Everywhere. Chips not *only* power personal computers, they are also the brains behind millions of cell phones, pagers and pacemakers; they run video games, satellite systems and Internet servers. The electronic marvels that have changed life so profoundly in the last 30 years owe their existence to the intelligence etched in chips. To keep up with the immense changes brought about by the Information Age, close to 300 billion chips are now being produced worldwide each year.

Corporate Brochure spread

APPLIED MATERIALS BASICS

APPLIED MATERIALS STYLE GUIDE

PRECISION IN SILICON

Typography:

Meta Plus Normal
Meta Plus Normal Italic
Meta Plus Medium
Meta Plus Medium Italic
Meta Plus Bold
Meta Plus Black

Caslon 540 Regular
Caslon 540 Italic
CASLON 540 ROMAN SMALL CAPS & FIGURES
Caslon 540 Italic Old Style Figures

Color Palette:

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Division Identifiers, Acronyms and Icons:

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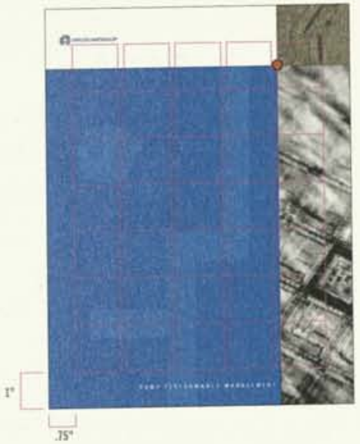
Mask - Isolating
PCI - Dopant Implantation
FPS - Product on Conveyer Belt
CPS - Customer Representation
PDC - Diagnostic
FPD - Flat Panel Display

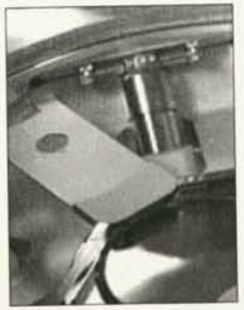
The Grid System:

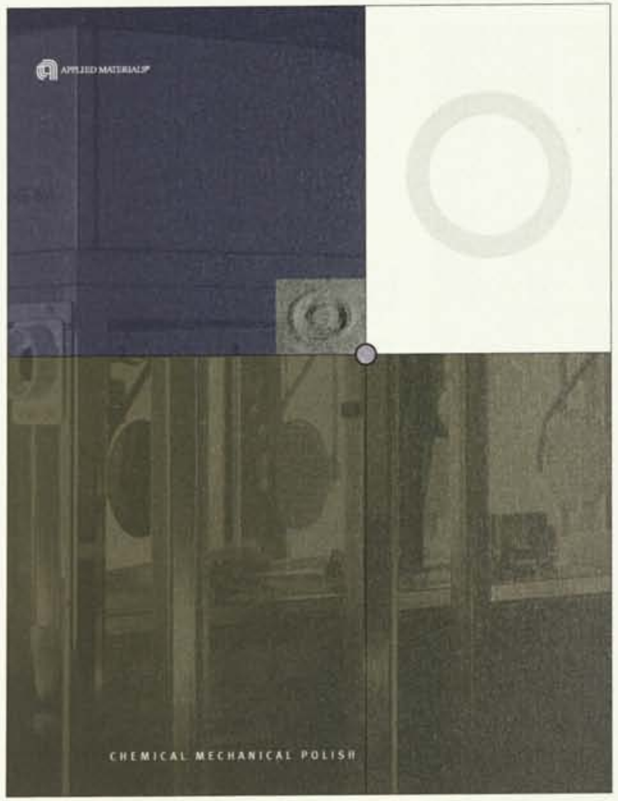
This 5-column grid was designed for flexibility. The addtion of a 14 row vertical grid, helps to maintain a consistent look throughout the system. The constant elements are called out below with their specific rules. Constant elements include: logo, precision rule graphic, photo icons, and graphic icons.



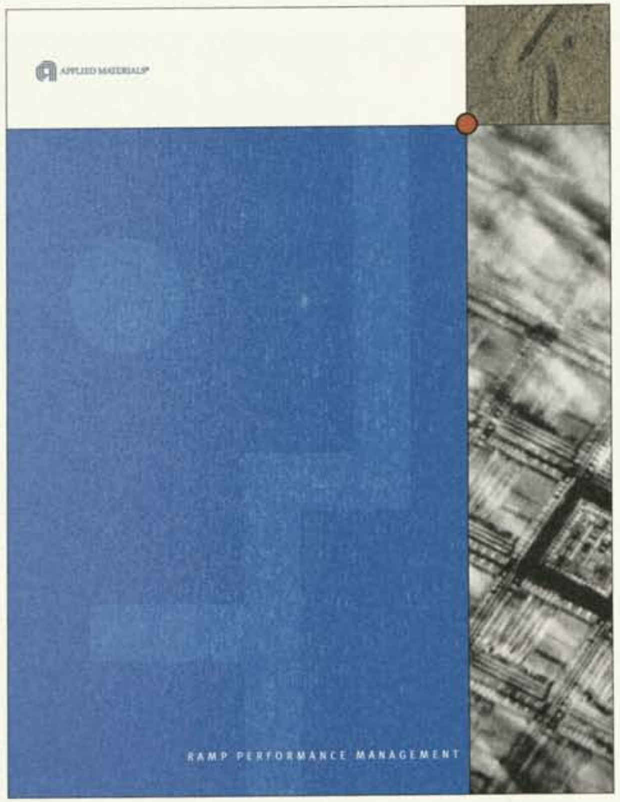
Treatment of the Photography:

The Photography is always tightly cropped, to create a more dramatic feel to the piece. It may be used as full color, black and white, or a highly saturated duotone

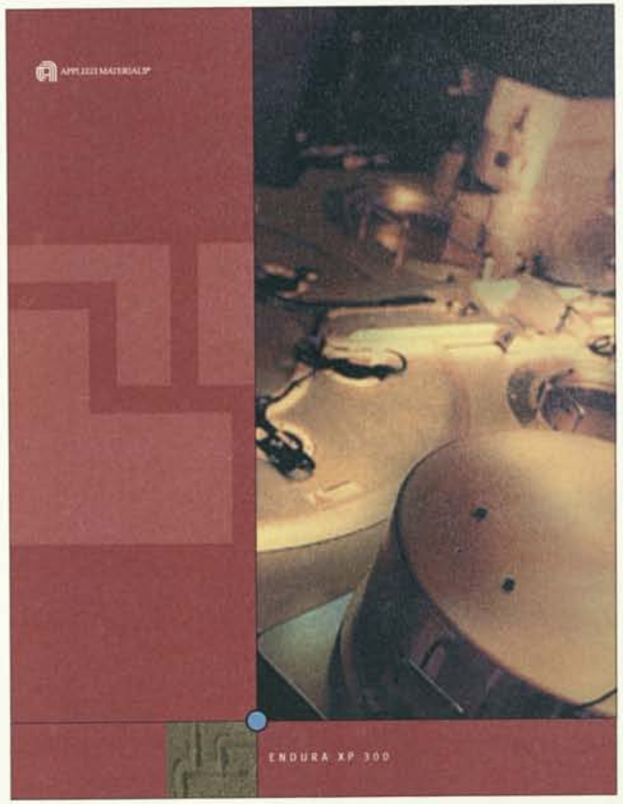




CMP Product Brochure cover

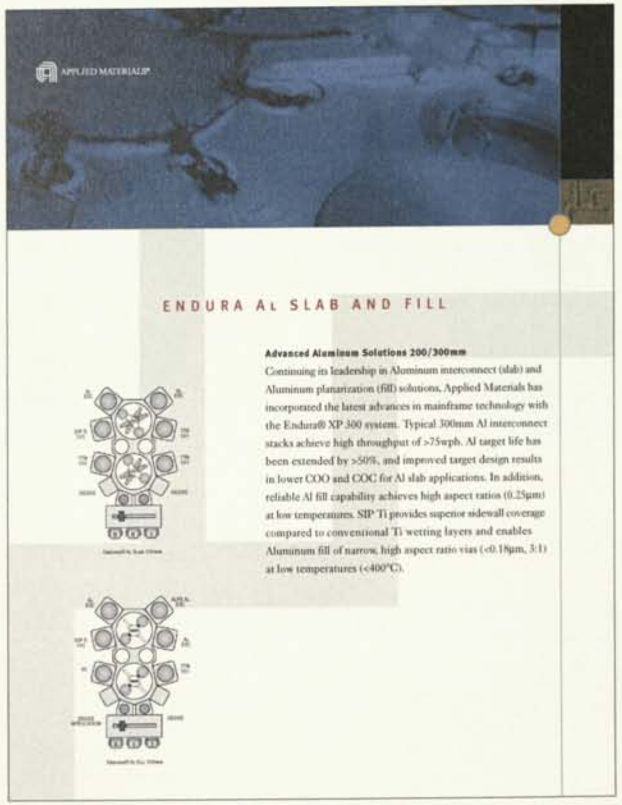


CPS Product Brochure cover


APPLIED MATERIALS

ENDURA XP 300

CPI Product Brochure cover

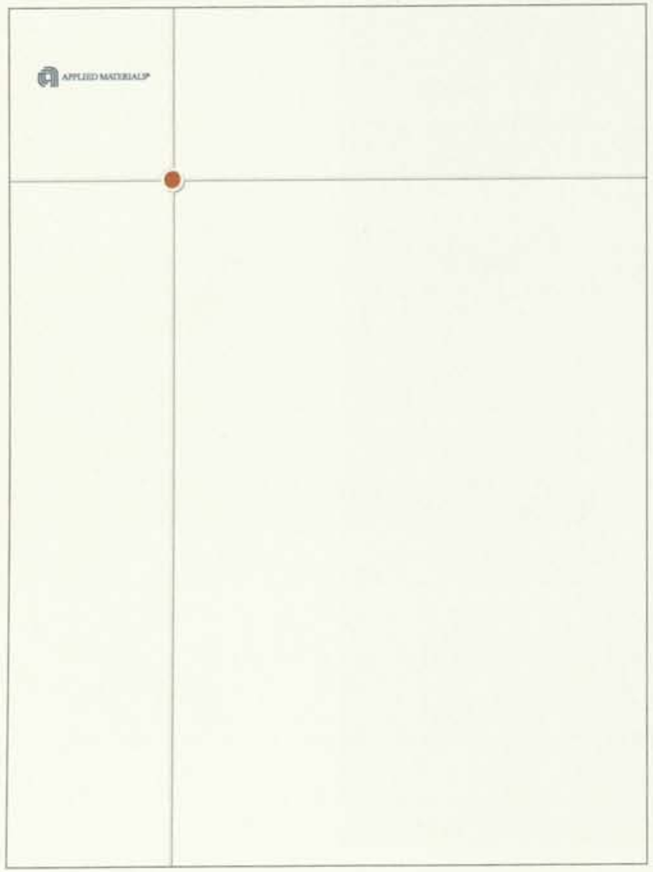

APPLIED MATERIALS

ENDURA AL SLAB AND FILL

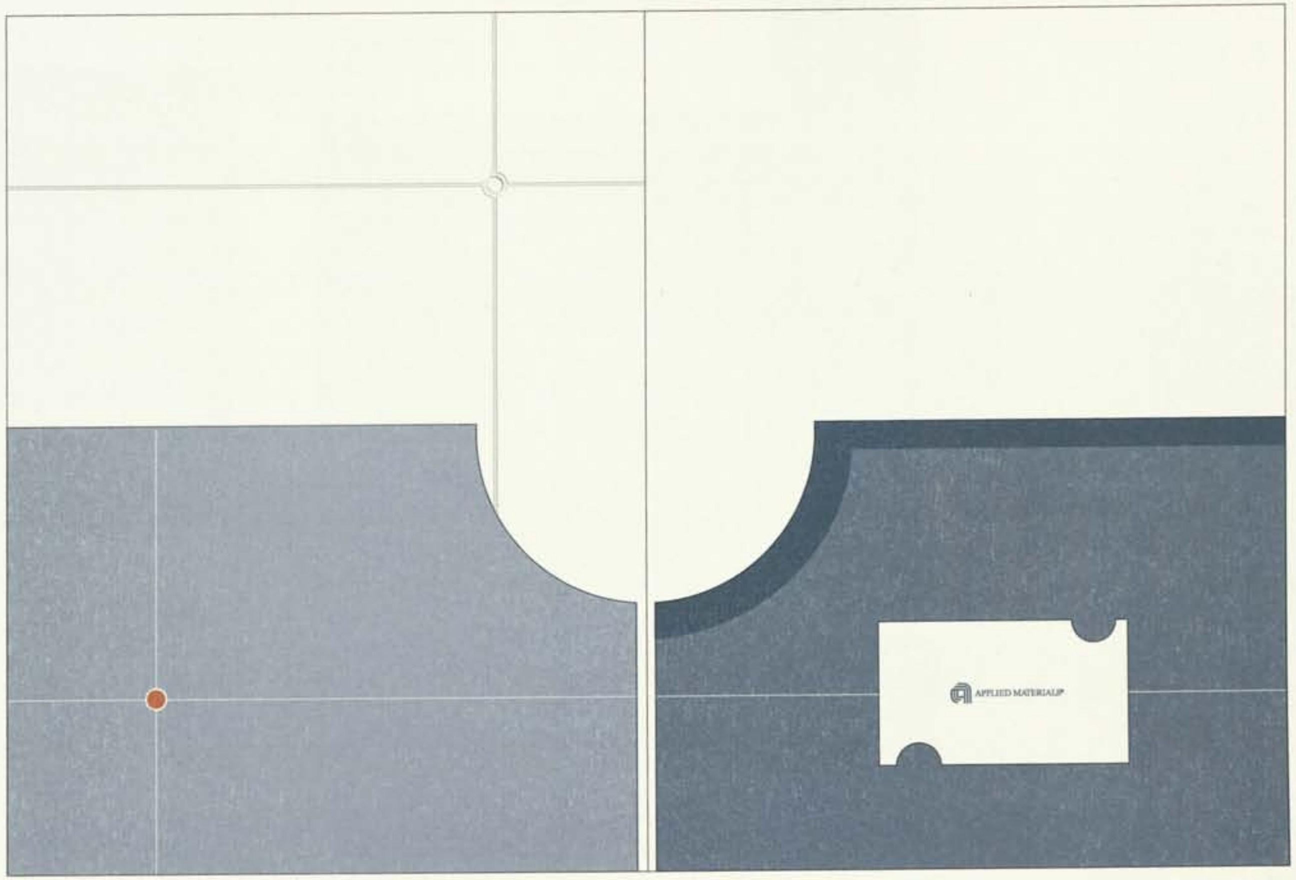
Advanced Aluminum Solutions 200/300mm

Continuing its leadership in Aluminum interconnect (slab) and Aluminum planarization (fill) solutions, Applied Materials has incorporated the latest advances in mainframe technology with the Endura® XP 300 system. Typical 300mm Al interconnect stacks achieve high throughput of >75wph. Al target life has been extended by >50%, and improved target design results in lower COO and COC for Al slab applications. In addition, reliable Al fill capability achieves high aspect ratios (0.25μm) at low temperatures. SIP Ti provides superior sidewall coverage compared to conventional Ti wetting layers and enables Aluminum fill of narrow, high aspect ratio vias (<0.18μm, 3:1) at low temperatures (<400°C).

CPI Product Datasheet



Corporate Folder cover



Corporate Folder interior

OUT OF THE BOX—INNOVATION AT EVERY LAYER

eleveneightyfivedesign

The Creative:

Corporate Brochure (cover and spread)

Corporate Folder (cover and interior)

Datasheet (front)

Product Brochures (divisional covers)

The Concept: “Out of the Box”/ Innovation at Every Layer

Achieving and maintaining leadership within an industry takes dedication to research and innovation. This concept highlights Applied's strength in these two areas with the theme “Out of the Box”/ Innovation At Every Layer. The layouts visually illustrate this theme by exploding type and imagery “out of” the page and allowing maximum versatility for divisional freedom within the system.

Core Values:

Applied Materials is the largest supplier of products and services to the global semiconductor industry and is one of the world's leading information infrastructure providers. Applied Materials enables Information for Everyone by helping semiconductor manufacturers produce more powerful, portable and affordable chips.

Target Audience:

Varies on the collateral pieces. Materials generally target the CIO, CFO or the technology decision makers within a chip making organization.

Primary Objective:

To create a recognizable, unique brand identity that is consistent in messaging and design. The Look and Feel needs to express AMAT's personality and position in a global marketplace.

Survey Results:

(a brief summary)

- To become more **approachable**
- **Less autonomy** among divisions
- Create **brand recognition**
- Continue to project **leadership** image
- **Humanizing** technical aspects of literature
- Photographs of **products/manufacturing**
- **Less conservative** image
- Moving towards a **brighter future**

APPLIED MATERIALS STYLE GUIDE

“OUT OF THE BOX”/ INNOVATION AT EVERY LAYER

Typography:

Sabon Roman
Sabon Small Caps & Old Style Figures
Sabon Italic
Sabon Bold
Sabon Bold Italic

Trade Gothic Regular
Trade Gothic Oblique
Trade Gothic Bold No. 2
Trade Gothic Bold No. 2
Trade Gothic Condensed No. 18
Trade Gothic Condensed No. 18

Color Palette:

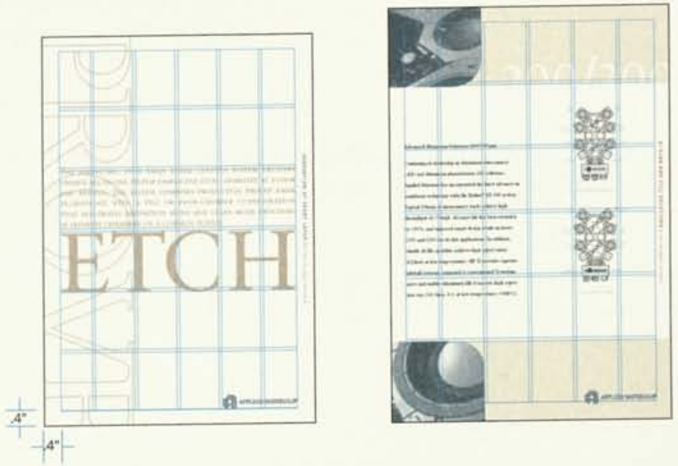
(m) represents metallic

Division Icon System:

(sampling)

The Grid System:

The basic Grid System is dividing the page into 6x6 rectangles which are used for positioning of elements within the page. There is also a 6 column grid, for text that fits into the Square grid system, any combination of the column grid is acceptable except a one column usage.



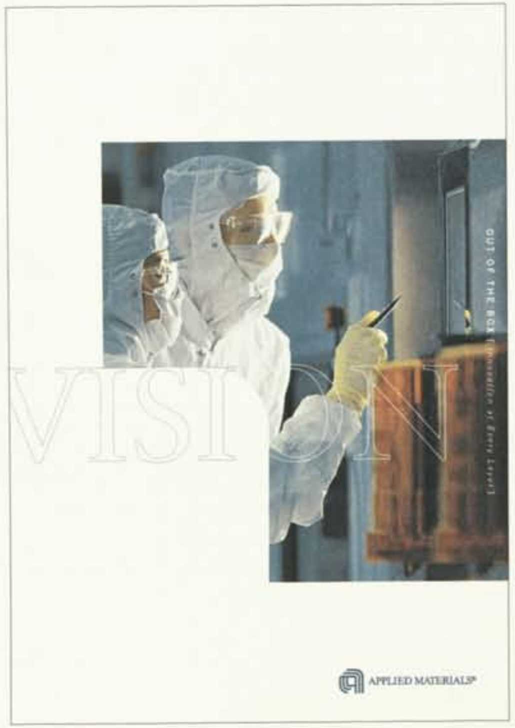
Treatment of the Photography:

In keeping with the concept of “Out of the Box”, photography is used uniquely on each piece. Whether black and white, monochromatic or full-color, the imagery must be compelling with dramatic crops, expansion off the page, or sequential.

Expansion off the page

Image Sequence
(timeline or video effect)

"OUT OF THE BOX"/ INNOVATION AT EVERY LAYER

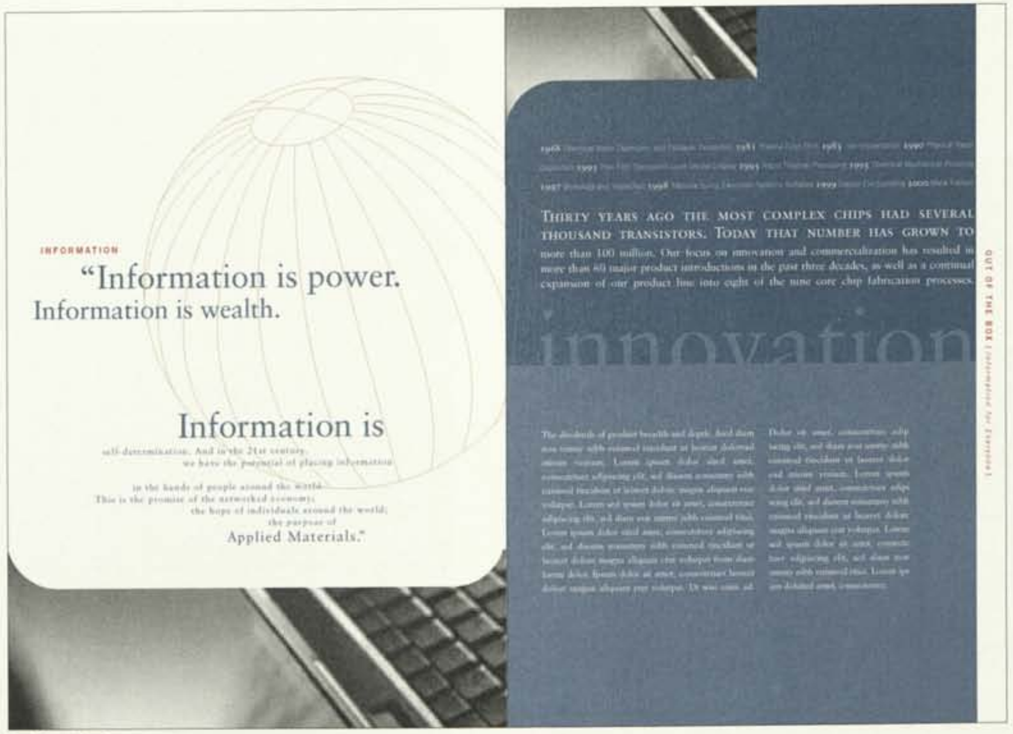


VISION

OUT OF THE BOX | Innovation at Every Layer]

APPLIED MATERIALS®

Cover Corporate Brochure, Size: 7 x 10



INFORMATION

"Information is power.
Information is wealth.

Information is
self-determination. And in the 21st century,
we have the potential of placing information
in the hands of people around the world.
This is the promise of the networked economy;
the hope of individuals around the world;
the purpose of
Applied Materials."

THIRTY YEARS AGO THE MOST COMPLEX CHIPS HAD SEVERAL THOUSAND TRANSISTORS. TODAY THAT NUMBER HAS GROWN TO more than 100 million. Our focus on innovation and commercialization has resulted in more than 40 major product introductions in the past three decades, as well as a continual expansion of our product line into eight of the nine core chip fabrication processes.

innovation

OUT OF THE BOX | Information for Everyone]

Spread Corporate Brochure

Front Cover

“OUT OF THE BOX”/ INNOVATION AT EVERY LAYER

THE DIELECTRIC ETCH EMAX ENTEK CENTURA SYSTEM DELIVERS UNIQUE ALL-IN-ONE SYSTEM DAMASCENE ETCH CAPABILITY AT 100NM AND BEYOND. THE SYSTEM COMBINES PRODUCTION PROVEN EMAX TECHNOLOGY WITH A TWO OR FOUR-CHAMBER CONFIGURATION THAT INTEGRATES DEPOSITION MODE AND CLEAN MODE PROCESSES IN SEPARATE CHAMBERS ON A COMMON SYSTEM.

ETCH

INNOVATION AT EVERY LAYER | *ETCH Product Group* |

APPLIED MATERIALS®

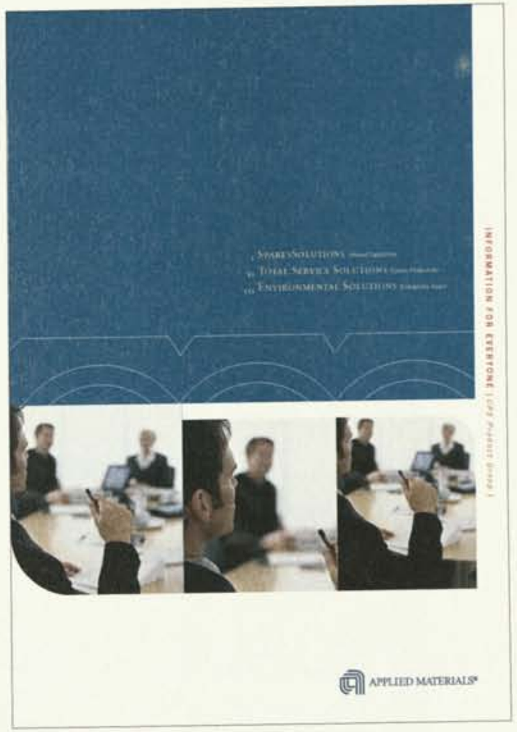
Cover Division Brochure, ETCH, Size: 7 x 10 (2-color)

OUT OF THE BOX | *PCI Product Group* |

PCI

APPLIED MATERIALS®

Cover Division Brochure, PCI, Size: 7 x 10



i SPARESOLUTIONS

ii TOTAL SERVICE SOLUTIONS

iii ENVIRONMENTAL SOLUTIONS

INFORMATION FOR EVERYONE | *CPS Product Group* |

APPLIED MATERIALS®

Cover Division Brochure, CPS, Size: 7 x 10

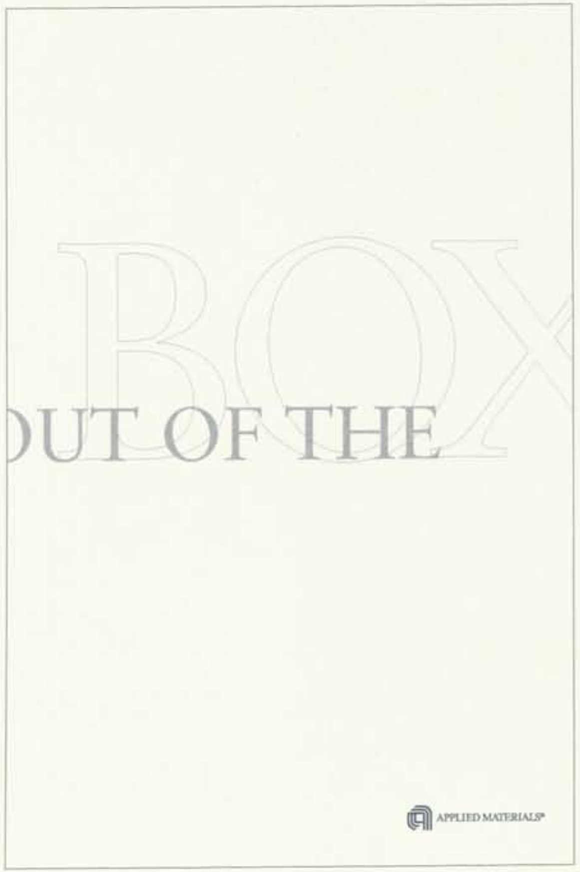
Cover Division Brochure, CPI, Size: 7 x 10

Advanced Aluminum Solutions 200/300mm

Continuing its leadership in Aluminum interconnect (*slab*) and Aluminum planarization (*fill*) solutions, Applied Materials has incorporated the latest advances in mainframe technology with the Endura® XP 300 system. Typical 300mm Al interconnect stacks achieve high throughput of >75wph. Al target life has been extended by >50%, and improved target design results in lower COO and COC for Al slab applications. In addition, reliable Al fill capability achieves high aspect ratios (0.25μm) at low temp-eratures. SIP Ti provides superior sidewall coverage compared to conventional Ti wetting layers and enables Aluminum fill of narrow, high aspect ratio vias (<0.18μm, 3:1) at low temperatures (<400 C).

Front Datasheet, CPI Division, Aluminum Solutions, Size: 7.5 x 11

“OUT OF THE BOX”/ INNOVATION AT EVERY LAYER



Cover Folder, Size: 8 x 12

Corporate Brochure

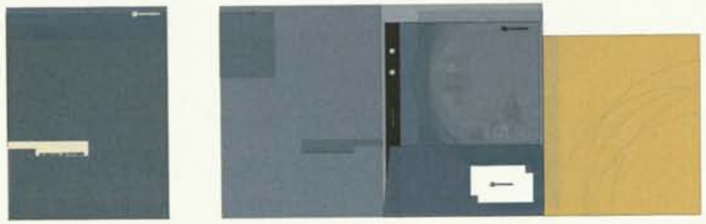
Interior Folder

INTEGRATION/CHIP MAKING AS ART

elevenseightyfivedesign

The Creative:

Corporate Brochure



Corporate Folder

Brochure Covers

Datasheets

The Concept: Integration/Chipmaking as Art

Applied Materials as a corporate entity brings together a tremendous number of divisions, each with a distinct personality and area of specialization. While each of these divisions is uniquely tailored to its particular market segment, they cooperate to form a "Total Solution." This look and feel combines the organic qualities of overlapping circles juxtaposed against strong geometric blocks, and a solid framework to represent the strong solution that Applied Materials offers.

Core Values:

Applied Materials is the largest supplier of products and services to the global semiconductor industry and is one of the world's leading information infrastructure providers. Applied Materials enables Information for Everyone by helping semiconductor manufacturers produce more powerful, portable and affordable chips.

Target Audience:

Varies on the collateral pieces. Materials generally target the CIO, CFO or the technology decision makers within a chip making organization.

Primary Objective:

To create a recognizable, unique brand identity that is consistent in messaging and design. The Look and Feel needs to express AMAT's personality and position in a global marketplace.

Survey Results:

(a brief summary)

- To become more **approachable**
- **Less autonomy** among divisions
- Create **brand recognition**
- Continue to project **leadership** image
- **Humanizing** technical aspects of literature
- **Less conservative** image
- Moving towards a **brighter future**

APPLIED MATERIALS STYLE GUIDE

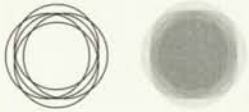
INTEGRATION/CHIPMAKING AS ART

Typography:

Trade Gothic Light
Trade Gothic Light Oblique
Trade Gothic
Trade Gothic Oblique
Trade Gothic Bold
Trade Gothic Bold Oblique
Trade Gothic Bold Two
Trade Gothic Bold Two Oblique

Sabon Regular
Sabon Regular Small Caps
Sabon Italic
Sabon Bold
Sabon Bold Italic

Icon System:



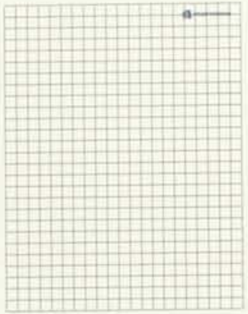
Color Palette:

The Grid System:

The Grid System divides the page into 1 cm squares. Images and shapes can fall into any combination on that grid. The text falls into two columns in one of the two options shown below.

Treatment of the Page and Graphic Elements

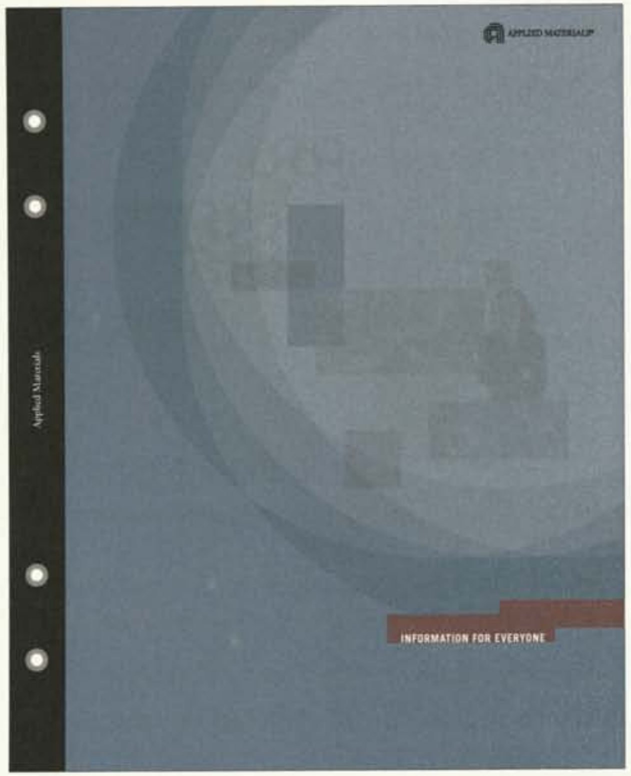
The structured grid provides a versitle and adaptable framework for developing a variety of collateral



A highly structured grid based on 1 cm squares is provides the framework for the open architecture of this collateral system. The logo always falls 1 cm from the top and 1 cm from the right.

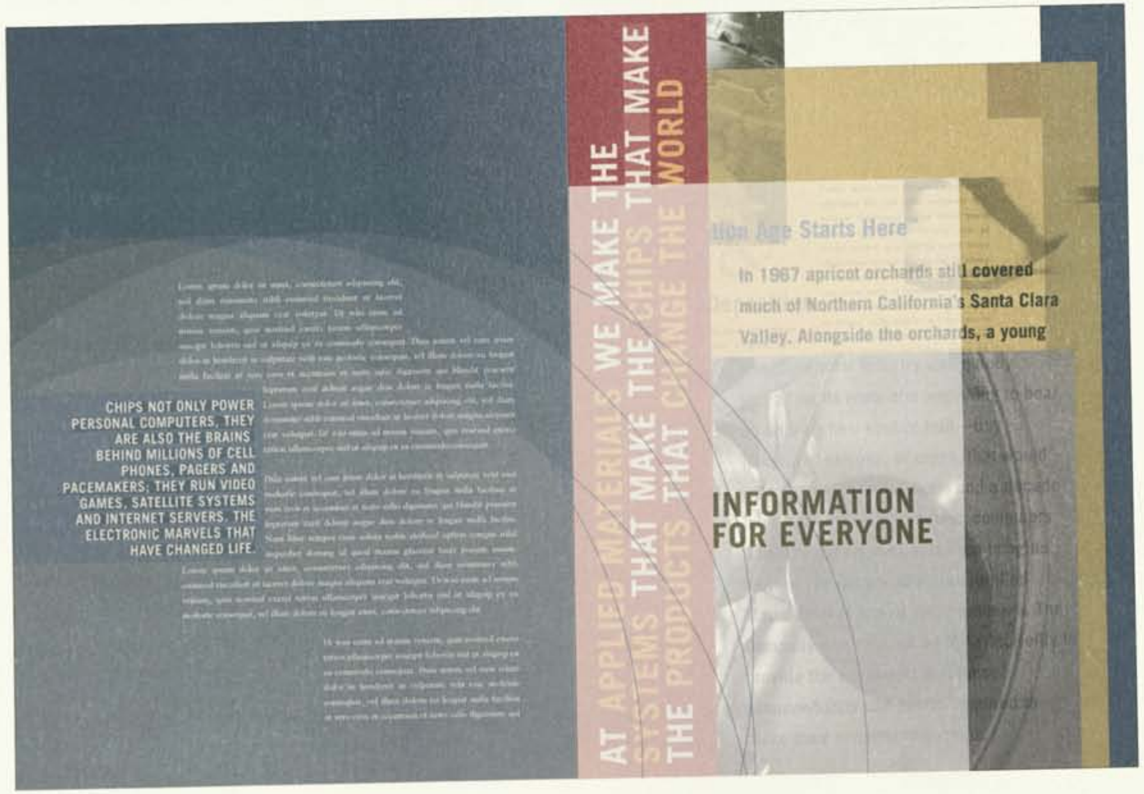
Grid may be used for a loose, organic arrangement of overlapping shapes.

Alternatively, the grid may be adapted into more rigid interpretation.



Corporate Brochure Cover with Vellum Outer Cover and Grommet Bindery
(Measures 22 cm x 27cm)

Corporate Brochure Cover with Vellum Outer Cover Opened



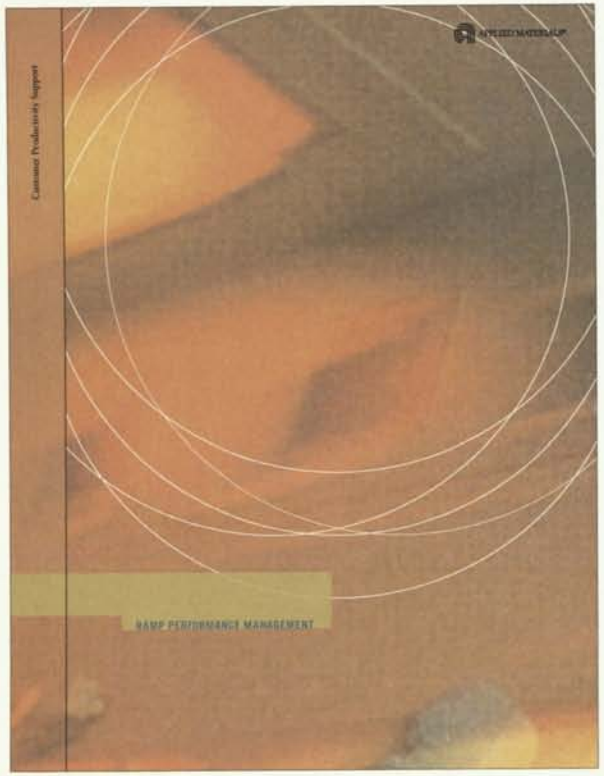
CHIPS NOT ONLY POWER PERSONAL COMPUTERS, THEY ARE ALSO THE BRAINS BEHIND MILLIONS OF CELL PHONES, PAGERS AND PACEMAKERS; THEY RUN VIDEO GAMES, SATELLITE SYSTEMS AND INTERNET SERVERS. THE ELECTRONIC MARVELS THAT HAVE CHANGED LIFE.

AT APPLIED MATERIALS WE MAKE THE SYSTEMS THAT MAKE THE CHIPS THAT MAKE THE PRODUCTS THAT CHANGE THE WORLD

tion Age Starts Here"

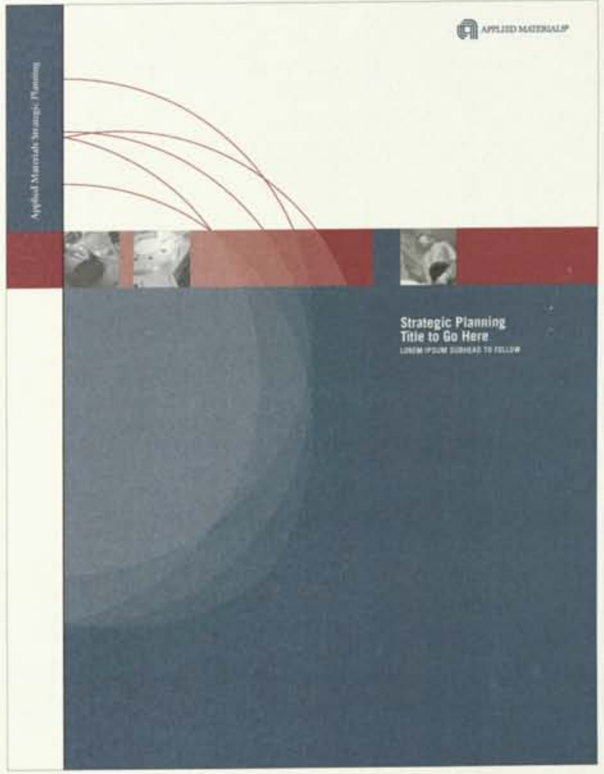
In 1967 apricot orchards still covered much of Northern California's Santa Clara Valley. Alongside the orchards, a young

Corporate Brochure Interior Spread
(With vellum pages allowing other pages to show through).



Product Division Brochure Cover (4-color) (21 cm x 27 cm)

Product Division Brochure Cover Variation (2-color) (21 cm x 27 cm)



Corporate Level Brochure Cover (21 cm x 27 cm)

CPI Datasheet

APPLIED MATERIALS®

200mm Endura® ALPS™ Cobalt for Advanced Silicides

Co, PVD AND INTEGRATED SYSTEMS & MODULES

FEATURES & BENEFITS

Datasheet Front (21 cm x 27 cm)

CPS Datasheet

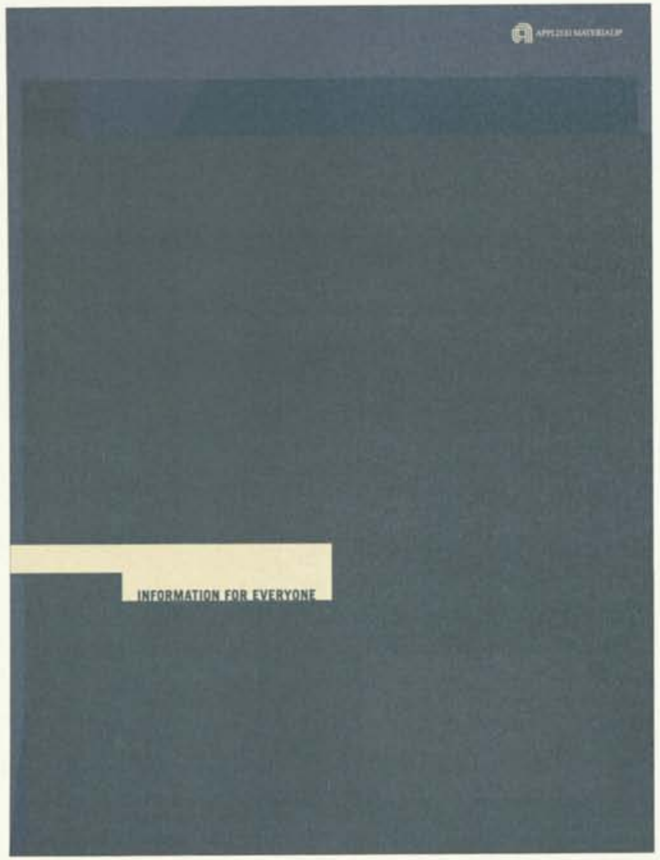
APPLIED MATERIALS®

Ramp Performance Management

"LOREM IPSUM DOLOR SIT AMET, CONSECTETUER ADIPISCING ELI, SED DIAM NONUMMY NIBH EUISMOD TINCIDUNT UT LAORE DOLOR."

RPM PRODUCTS

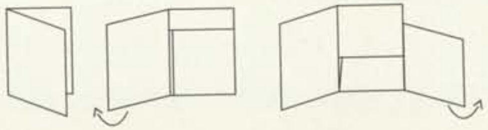
Datasheet Front Variation (3-color) (21 cm x 27 cm)



First Panel Opened made of vellum

INTEGRATION/CHIPMAKING AS ART

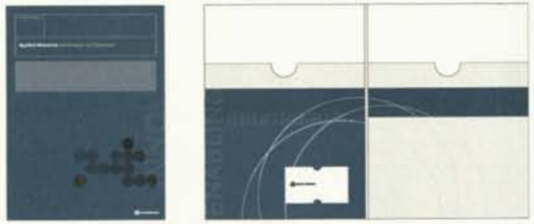
Interior of Corporate Folder



CUSTOMIZATION AND SCALABILITY

The Creative:

Corporate Brochure



Corporate Folder

CPI Data sheet

Product Brochure Covers

The Concept: Customization and Scalability

The circular pattern represents customization and scalability across all of Applied Materials' product offerings. A graphic pattern and icon are assigned to each division to be used as supporting textures and product differentiation. Product photography is used throughout to showcase Applied Materials' fabrication equipment. People photography will also be used as a secondary element to communicate the human side of Applied Materials.

Core Values:

Applied Materials is the largest supplier of products and services to the global semiconductor industry and is one of the world's leading information infrastructure providers. Applied Materials enables Information for Everyone by helping semiconductor manufacturers produce more powerful, portable and affordable chips.

Target Audience:

Varies on the collateral pieces. Materials generally target the CIO, CFO or the technology decision makers within a chip making organization.

Primary Objective:

To create a recognizable, unique brand identity that is consistent in messaging and design. The Look and Feel needs to express AMAT's personality and position in a global marketplace.

Survey Results:

(a brief summary)

- To become more **approachable**
- **Less autonomy** among divisions
- Create **brand recognition**
- Continue to project **leadership** image
- **Humanizing** technical aspects of literature
- **Less conservative** image
- Moving towards a **brighter future**

APPLIED MATERIALS STYLE GUIDE

CUSTOMIZATION AND SCALABILITY

Typography:

AG Buch Light
AG Buch Light Italic
AG Buch Regular
AG Buch Italic
AG Buch Medium
AG Buch Medium Italic

AG Buch Bold
AG Buch Bold Italic

Minion Regular
Minion Regular Small Caps
Minion Regular Italic
Minion Semibold
Minion Semibold Small Caps
Minion Semibold Italic
Minion Black

Color Palette:

PMS 5405 · PMS 5445 · PMS 5425 · PMS 458 · PMS 110 · PMS 138 · PMS 1805 · PMS 1815 · PMS 690 · PMS 5275 · PMS 2748 · PMS 660 · PMS 653

PMS 577 · PMS 390 · PMS 370 · PMS 7459 · Cool Grey2 · PMS 444

Metallics

PMS 8201 · PMS 8281 · PMS 877

Division Icons:

CPI
Cu, PVD and Integrated Systems and Modules
Metal atoms deposited on the wafer surface

CPS
Customer Productivity Support
Customer Service

DSM
Dielectric Systems and Modules
Insulating material deposited on the wafer surface

ETCH
Removing selected materials

PDC
Process Diagnostics and control
Quality control

FPS
Factory Productivity Solutions
Charting productivity

CMP
Chemical Mechanical Polishing
Flattening the wafer surface

MASK
Projecting circuit pattern

PCI
Parametric and Conductive Implant
Dopants penetrating the wafer surface

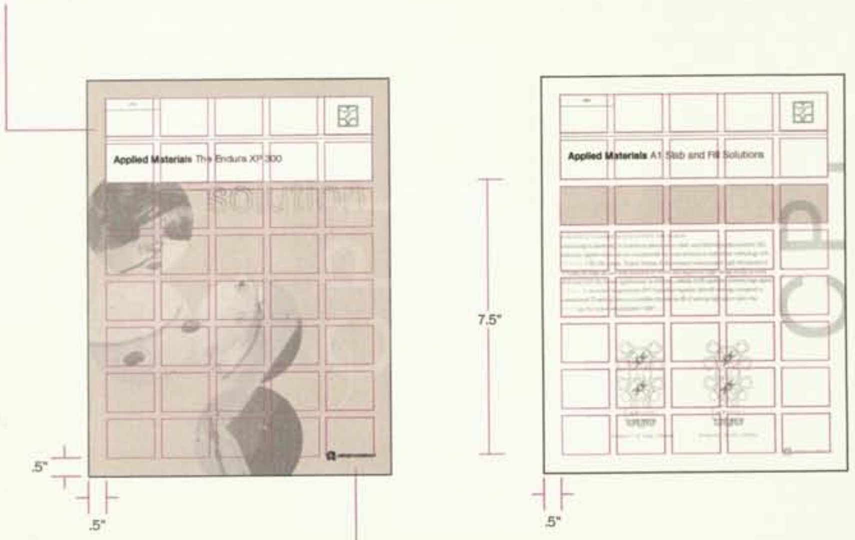
TCG
Transistor and Capacitor
Subjecting the wafer to a burst of heat

DISPLAY
Display Business Sector
Flat screen monitor

The Grid System:

The basic grid system divides the page into 5x8 squares, providing a flexible grid system to position images and text on the page.

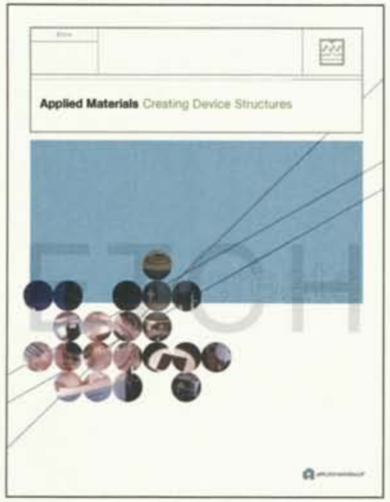
Grid lock-up stays constant in the look and feel. The elements inside the grid include: division name, division icon, and collateral title



Logo must always be placed on the bottom right hand corner of the piece.

Treatment of the Photography:

Photography is treated in black and white, color, and duotone. Photography can be masked inside circle cluster or it can be treated as a full bleed image.



Applied Materials Creating Device Structures

ETCH

Color photography masked inside circular cluster.

The semiconductor industry soon proved so fertile it not only transformed the sleepy Santa Clara Valley into "Silicon Valley," launching the Information Age, but spread far and wide across the globe. Driven first by the electronics industry, then rocketed upwards by the advent of personal computers, the chip industry exploded from a $2 billion dollar industry in the late 1960s to over $100 billion today.

Black and white photography treated with bleeds.

Key Attributes:

Each division will have its own list of key attributes to be used as a graphic element in the collateral system.

innovate enabling turnkey connect create

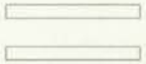
Division Line Textures:

A graphic pattern is assigned to each division to be used as supporting textures and product differentation.

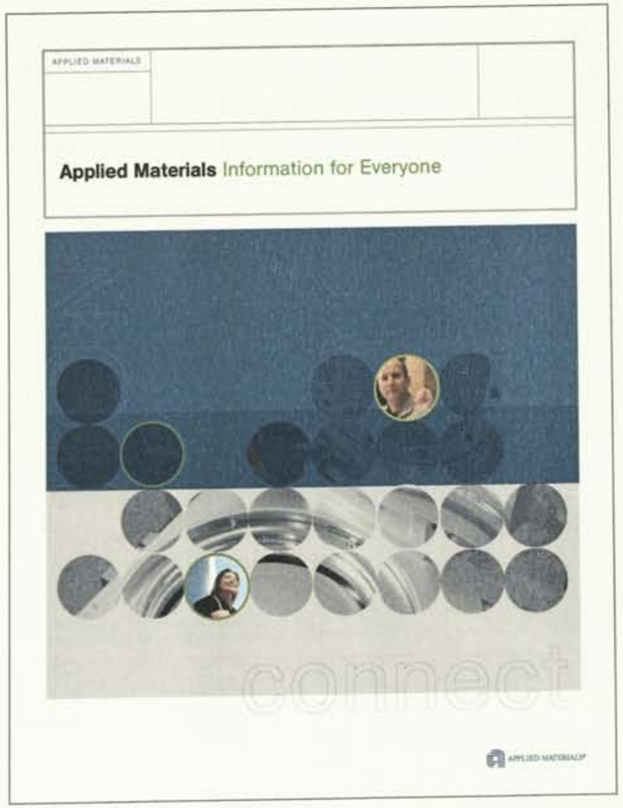
Corporate
(total solution)

ETCH
(etching the surface)

CPI
(metal atom deposits)



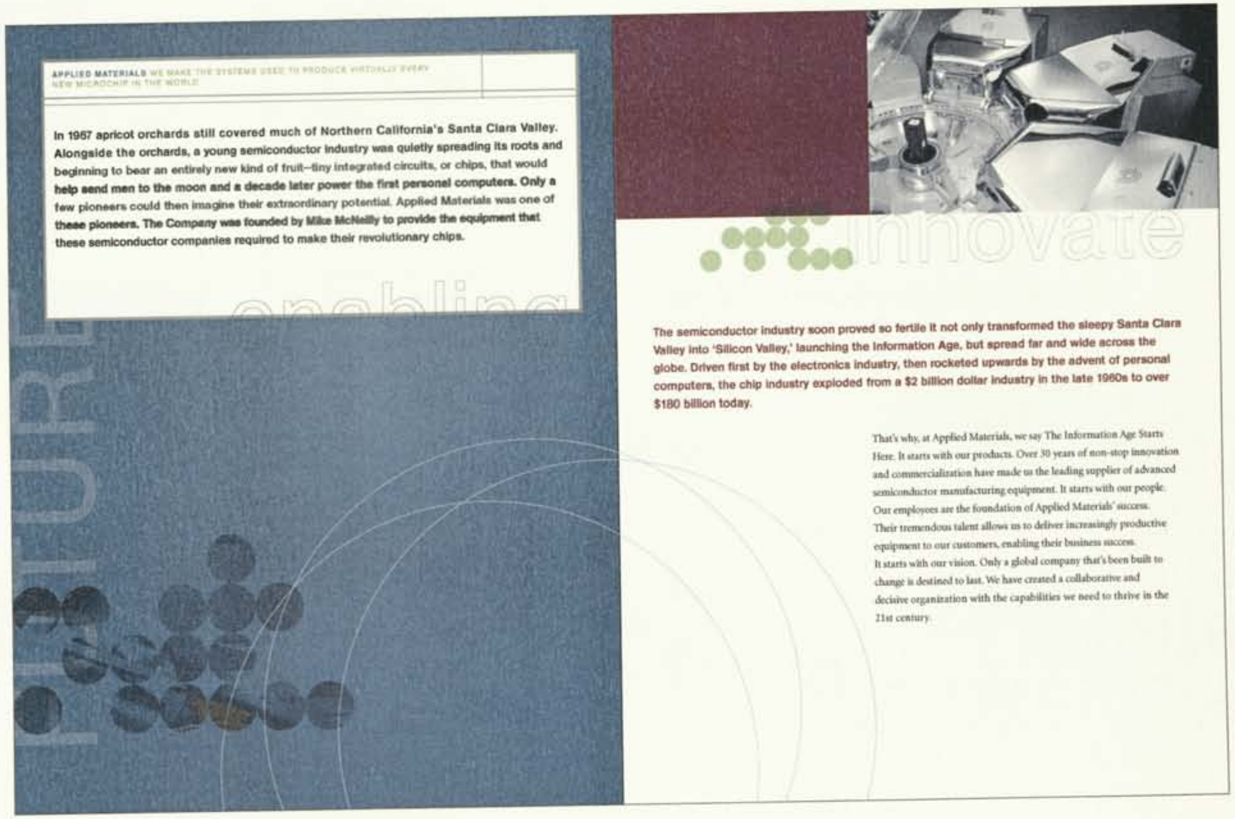
DSM
(insulating material)



APPLIED MATERIALS

Applied Materials Information for Everyone

Corporate Brochure Cover



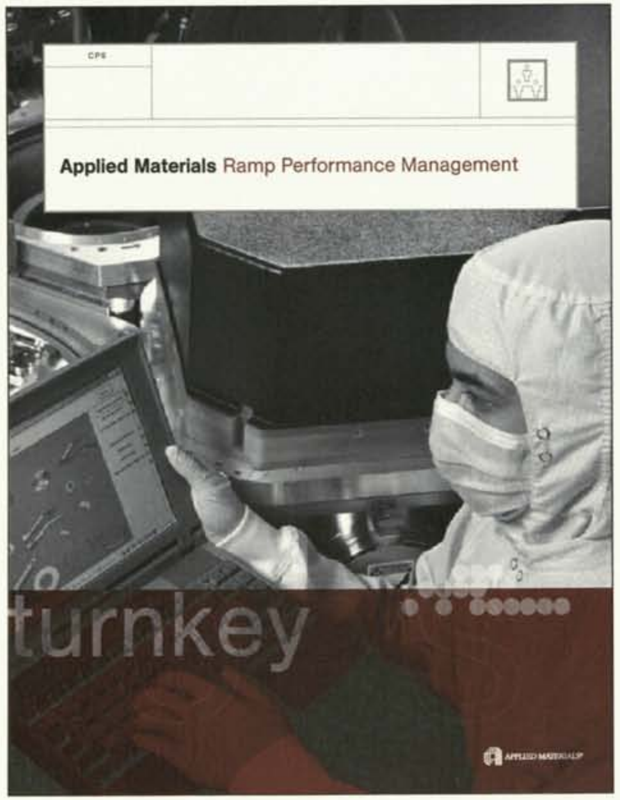
APPLIED MATERIALS WE MAKE THE SYSTEMS USED TO PRODUCE VIRTUALLY EVERY NEW MICROCHIP IN THE WORLD

In 1967 apricot orchards still covered much of Northern California's Santa Clara Valley. Alongside the orchards, a young semiconductor industry was quietly spreading its roots and beginning to bear an entirely new kind of fruit—tiny integrated circuits, or chips, that would help send men to the moon and a decade later power the first personal computers. Only a few pioneers could then imagine their extraordinary potential. Applied Materials was one of these pioneers. The Company was founded by Mike McNeilly to provide the equipment that these semiconductor companies required to make their revolutionary chips.

The semiconductor industry soon proved so fertile it not only transformed the sleepy Santa Clara Valley into 'Silicon Valley,' launching the Information Age, but spread far and wide across the globe. Driven first by the electronics industry, then rocketed upwards by the advent of personal computers, the chip industry exploded from a $2 billion dollar industry in the late 1960s to over $180 billion today.

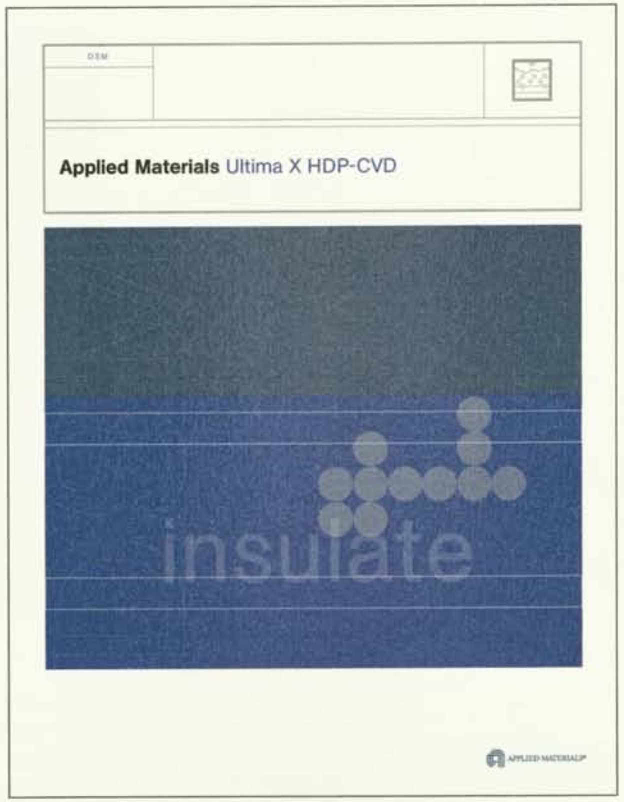
That's why, at Applied Materials, we say The Information Age Starts Here. It starts with our products. Over 30 years of non-stop innovation and commercialization have made us the leading supplier of advanced semiconductor manufacturing equipment. It starts with our people. Our employees are the foundation of Applied Materials' success. Their tremendous talent allows us to deliver increasingly productive equipment to our customers, enabling their business success. It starts with our vision. Only a global company that's been built to change is destined to last. We have created a collaborative and decisive organization with the capabilities we need to thrive in the 21st century.

Inside Spread



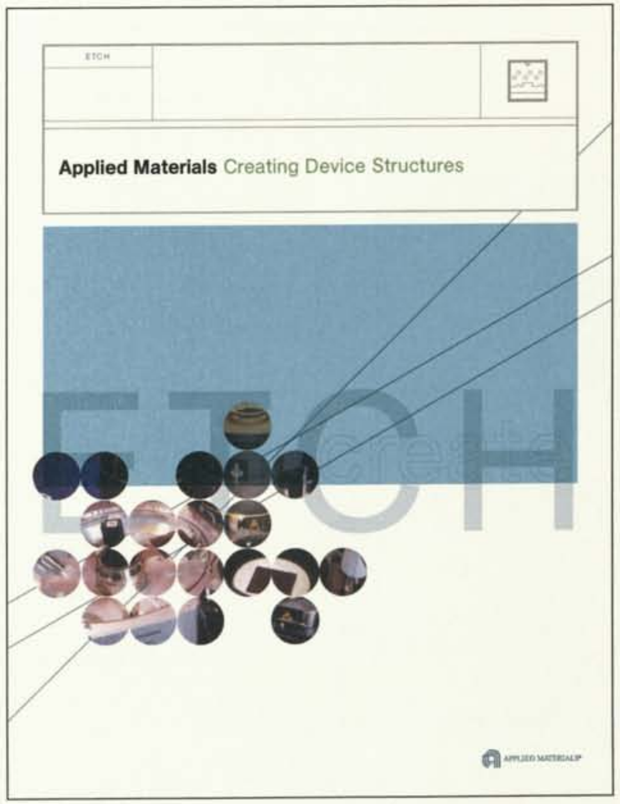
CPS

Applied Materials Ramp Performance Management



DSM

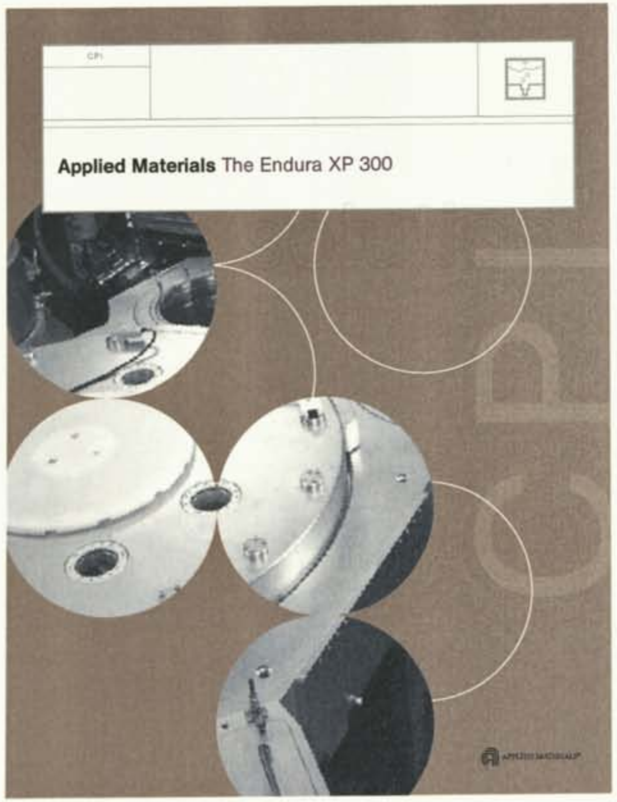
Applied Materials Ultima X HDP-CVD



ETCH

Applied Materials Creating Device Structures

Product Brochure Covers

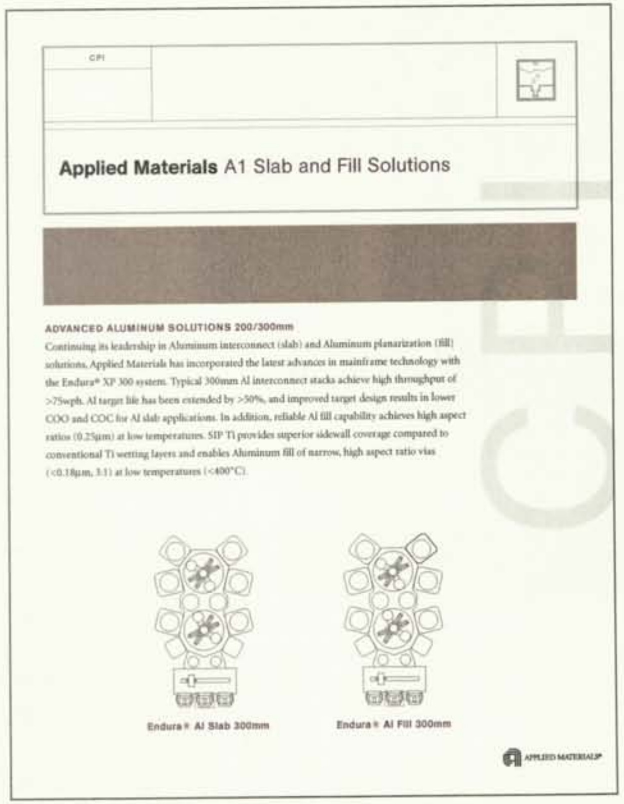


CPI

Applied Materials The Endura XP 300

APPLIED MATERIALS

CPI Product Brochure Cover



CPI

Applied Materials Al Slab and Fill Solutions

ADVANCED ALUMINUM SOLUTIONS 200/300mm

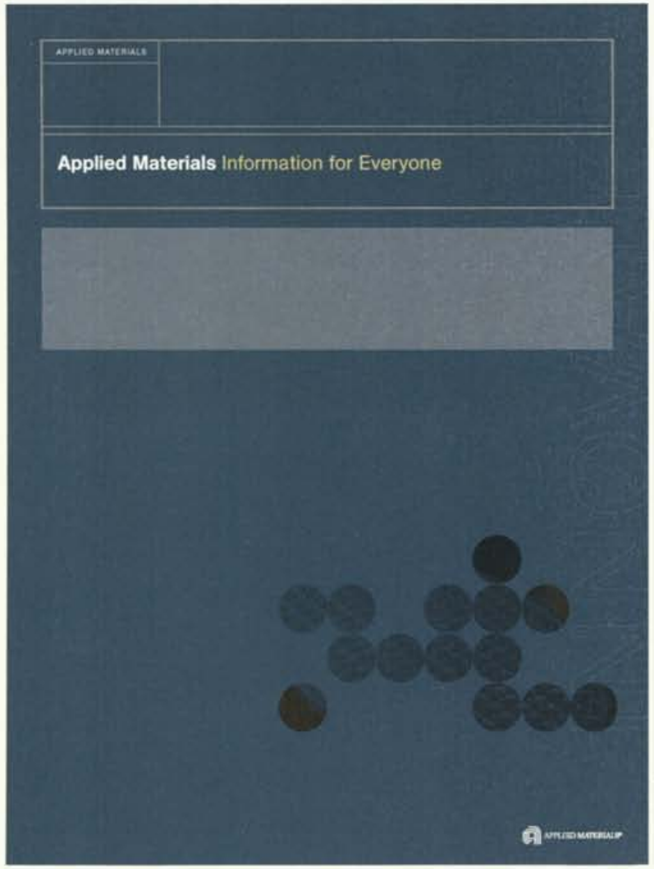
Continuing its leadership in Aluminum interconnect (slab) and Aluminum planarization (fill) solutions, Applied Materials has incorporated the latest advances in mainframe technology with the Endura® XP 300 system. Typical 300mm Al interconnect stacks achieve high throughput of >75wph. Al target life has been extended by >50%, and improved target design results in lower COO and COC for Al slab applications. In addition, reliable Al fill capability achieves high aspect ratios (0.25μm) at low temperatures. SIP Ti provides superior sidewall coverage compared to conventional Ti wetting layers and enables Aluminum fill of narrow, high aspect ratio vias (<0.18μm, 3:1) at low temperatures (<400°C).

Endura® Al Slab 300mm

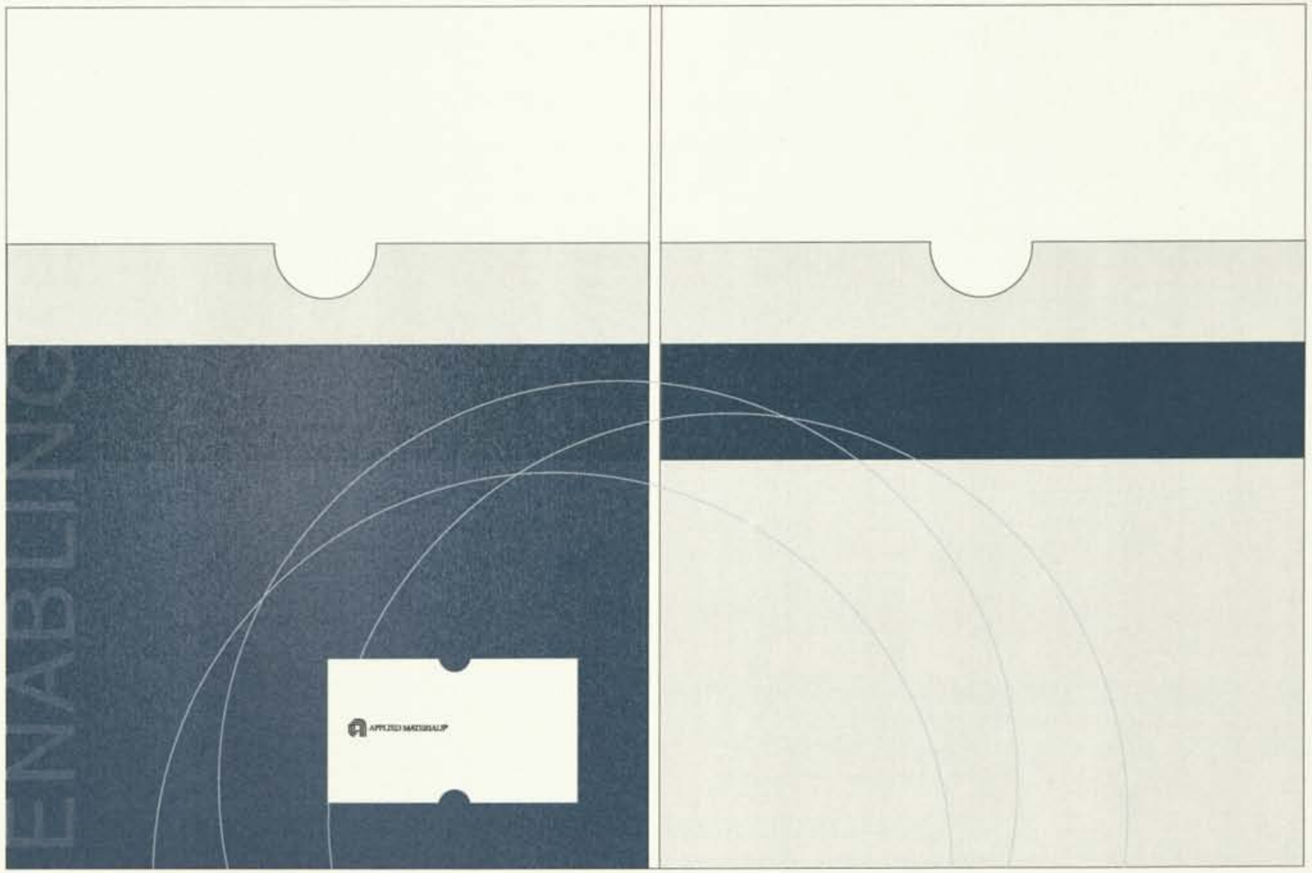
Endura® Al Fill 300mm

APPLIED MATERIALS

CPI Product Datasheet



Corporate Folder Cover



Inside Folder

PROCESS/LAYERS

eleveneightyfivedesign

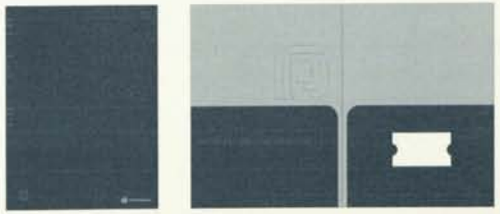
The Creative:

Corporate Brochure and Spread

Division Brochure Covers

Division Brochure Covers

Datasheets



Folder and Folder Interior

The Concept: Process/Layers

The chipmaking process is multi-layered. This multilevel concept is translated literally into this design system using a grid of horizontal lines. The system can be used to show a "detail" or expand to show the many "layers" of complexity within this manufacturing process.

Core Values:

Applied Materials is the largest supplier of products and services to the global semiconductor industry and is one of the world's leading information infrastructure providers. Applied Materials enables Information for Everyone by helping semiconductor manufacturers produce more powerful, portable and affordable chips.

Target Audience:

Varies on the collateral pieces. Materials generally target the CIO, CFO or the technology decision makers within a chip making organization.

Primary Objective:

To create a recognizable, unique brand identity that is consistent in messaging and design. The Look and Feel needs to express Appplied Materials's personality and position in a global marketplace.

Survey Results:

(a brief summary)

- To become more **approachable**
- **Less autonomy** among divisions
- Create **brand recognition**
- Continue to project **leadership** image
- **Humanizing** technical aspects of literature
- **Less conservative** image
- Moving towards a **brighter future**

APPLIED MATERIALS BASICS

APPLIED MATERIALS STYLE GUIDE

PROCESS/LAYERS

Typography:

ITC Stone Sans Medium	ITC Stone Serif Medium
ITC Stone Sans Italic	*ITC Stone Serif Italic*
ITC Stone Sans Semibold	**ITC Stone Serif Semibold**
ITC Stone Sans Semibold Italic	***ITC Stone Serif Semibold Italic***
ITC Stone Sans Bold	**ITC Stone Serif Bold**
ITC Stone Sans Bold Italic	***ITC Stone Serif Bold Italic***

Color Palette:

PMS 661	PMS 5405	PMS 5425	PMS 5445	PMS 3025	PMS 5555	PMS 5575	PMS 5595
PMS 704	PMS 181	PMS 160	PMS 723	PMS 2603	PMS 669	PMS 667	PMS 664
PMS 371	PMS 5825	PMS 5845	PMS 5875	PMS 131	PMS 132	PMS 117	PMS 110

Icons:

Icons will share a common rule. All are square with the exception of Corporate, which is circular.

Corporate: Globe

Etch: Removal from surface

PCI: Dopant Implantation

PDC: Diagnostic

CPI: Metal Deposition

CMP: Polishing

FPS: Factory Productivity

Mask: Isolating

DSM: Insulation Deposition

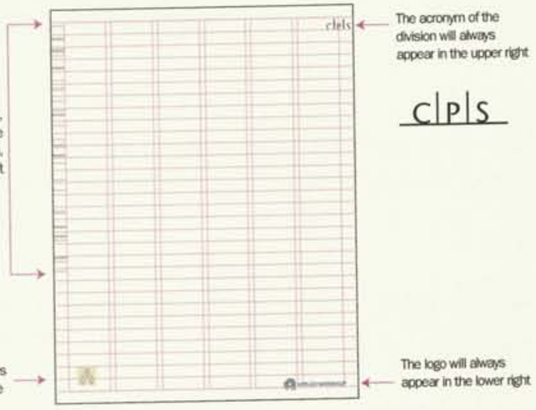
TCG: Implantation of Pos/Neg

CPS: Customer Service

Display: Flat panel displays

The Grid System:

The Grid System is divided up into horizontal equidistant strips. All artwork must be based on this horizontal system. A vertical grid, divided up in six columns, is the system for type placement.



The acronym of the division will always appear in the upper right

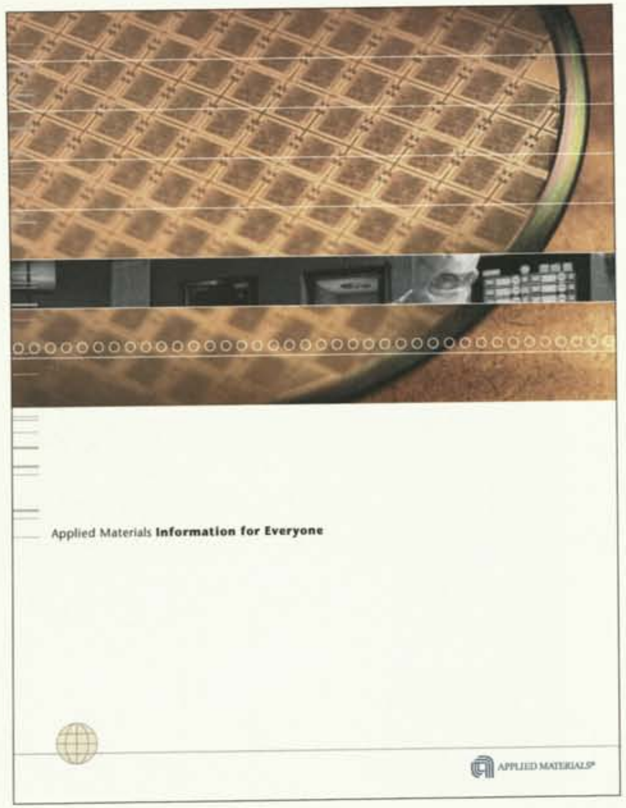
A row of tick marks, an abstract reference to the concept of precision, will always appear on the left

An icon will always appear on the bottom rule

The logo will always appear in the lower right

Treatment of the Photography:

Photography may be used as 4-color, duotones, or black and white.



Applied Materials **Information for Everyone**

Corporate Brochure Cover

TECHNOLOGY FOR THE FUTURE

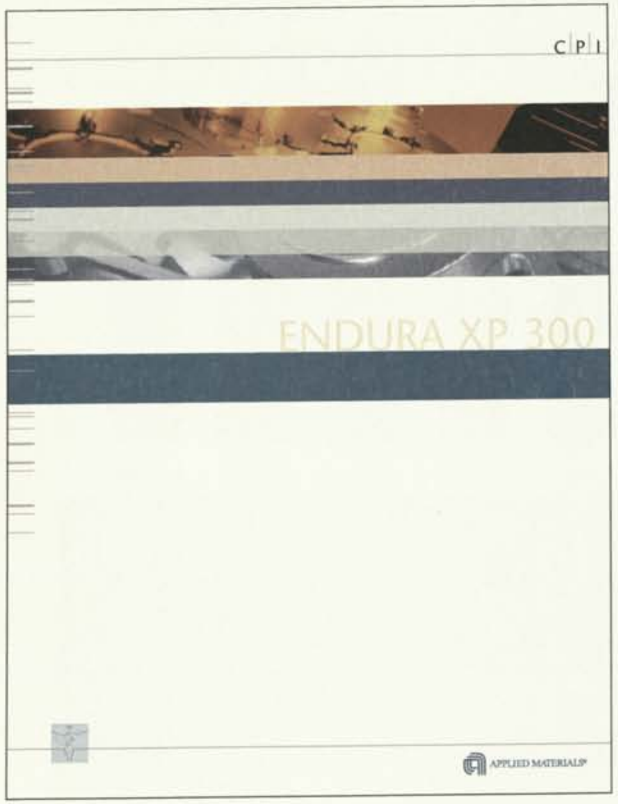
In 1967 apricot orchards still covered much of Northern California's Santa Clara Valley. Alongside the orchards, a young semiconductor industry was quietly spreading its roots and beginning to bear an entirely new kind of fruit—tiny integrated circuits, or chips, that would help send men to the moon and a decade later power the first personal computers. Only a few pioneers could then imagine their extraordinary potential. Applied Materials was one of these pioneers. The Company was founded by Mike McNeilly to provide the equipment that these semiconductor companies required to make their revolutionary chips.

The semiconductor industry soon proved so fertile it not only transformed the sleepy Santa Clara Valley into 'Silicon Valley,' launching the Information Age, but spread far and wide across the globe. Driven first by the electronics industry, then rocketed upwards by the advent of personal computers, the chip industry exploded from a $2 billion dollar industry in the late 1960s to over $180 billion today. As semiconductor fabrication boomed, Applied Materials also blossomed. Growing from a single-product business with $100,000 in first-year sales, and expanding rapidly under the dynamic leadership of CEO Jim Morgan (who joined the company in 1976), we have become the world's largest supplier of semiconductor manufacturing equipment.

Every chip. Every day. Everywhere. Chips not only power personal computers, they are also the brains behind millions of cell phones, pagers and pacemakers; they run video games, satellite systems and Internet servers. The electronic marvels that have changed life so profoundly in the last 30 years owe their existence to the intelligence etched on chips. To keep up with the immense changes brought about by the Information Age, close to 300 billion chips are now being produced worldwide each year.

To satisfy this demand, virtually every semiconductor manufacturer in the world uses Applied Materials equipment to make their chips. Today, Applied Materials systems are at work around the clock producing chips for our customers across Asia, Europe and North America.

Corporate Brochure Interior Spread

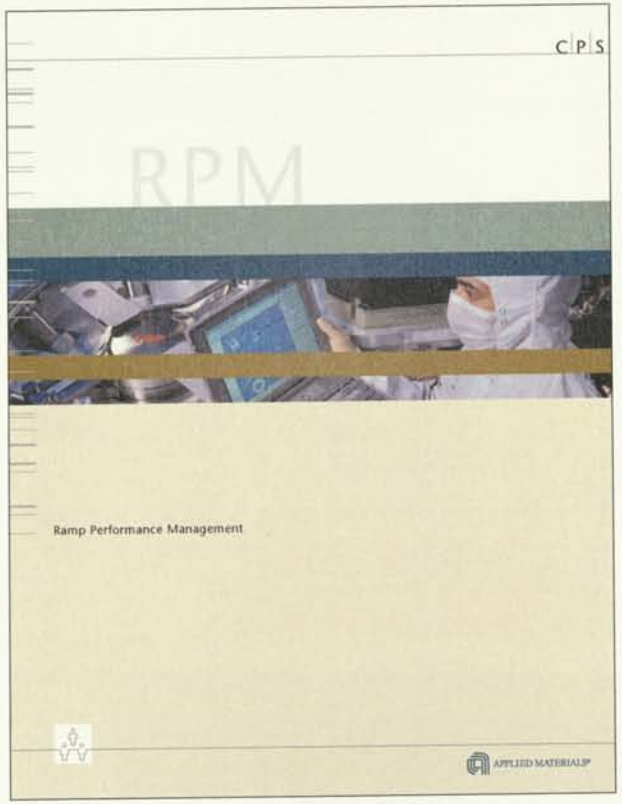


CPI

ENDURA XP 300

APPLIED MATERIALS

CPI Division Brochure



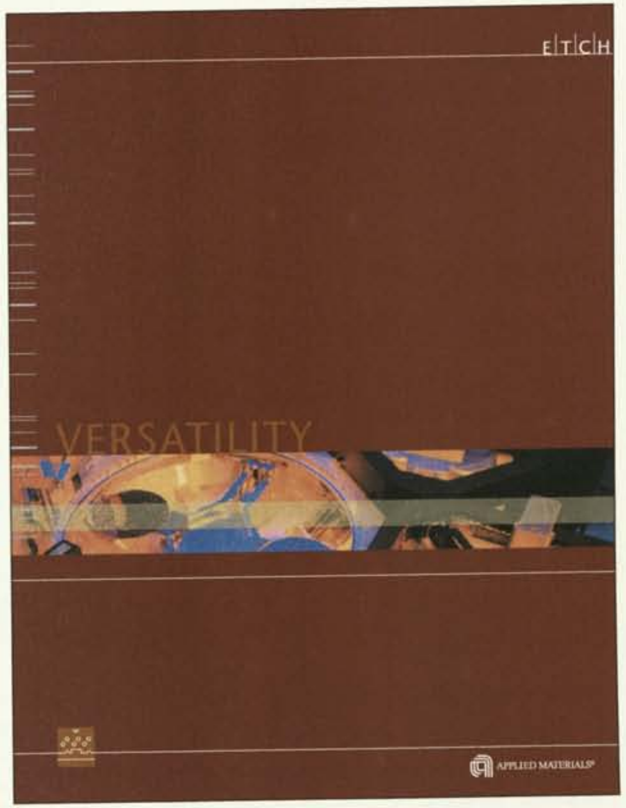
CPS

RPM

Ramp Performance Management

APPLIED MATERIALS

CPS Division Brochure

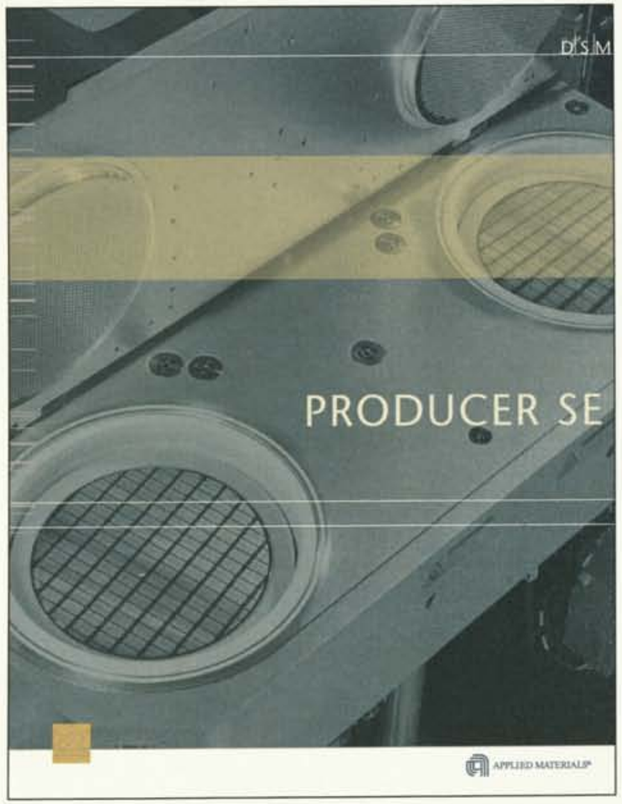


ETCH

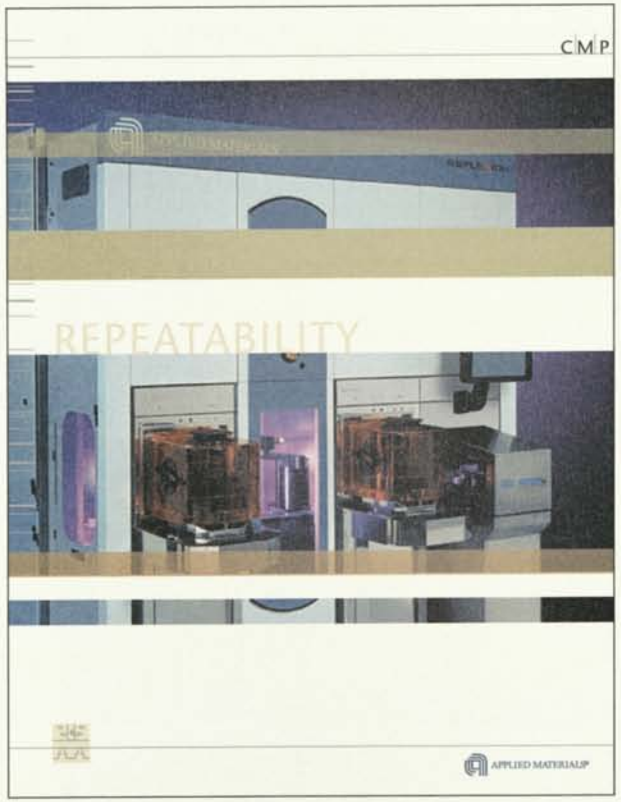
VERSATILITY

APPLIED MATERIALS

Etch Division Brochure

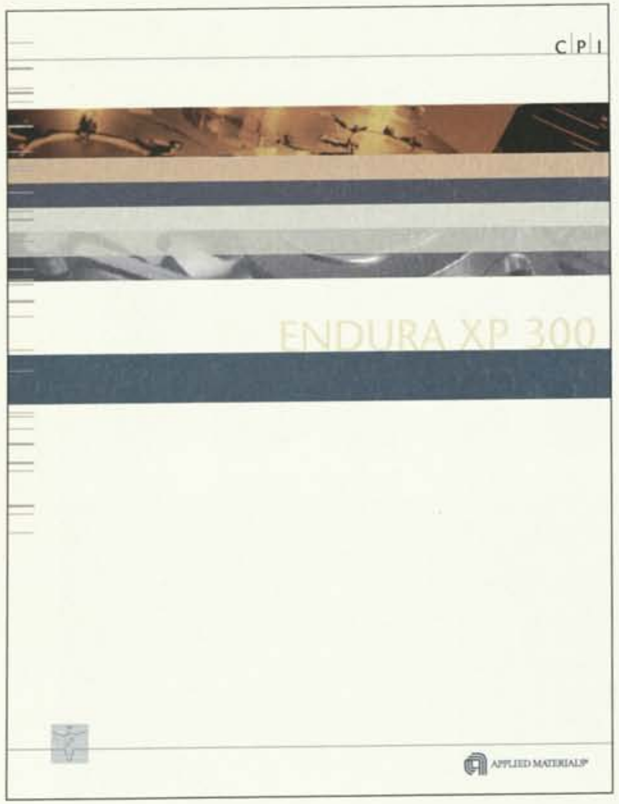


DSM Division Brochure



CMP Division Brochure

PDC Division Brochure — two-color option

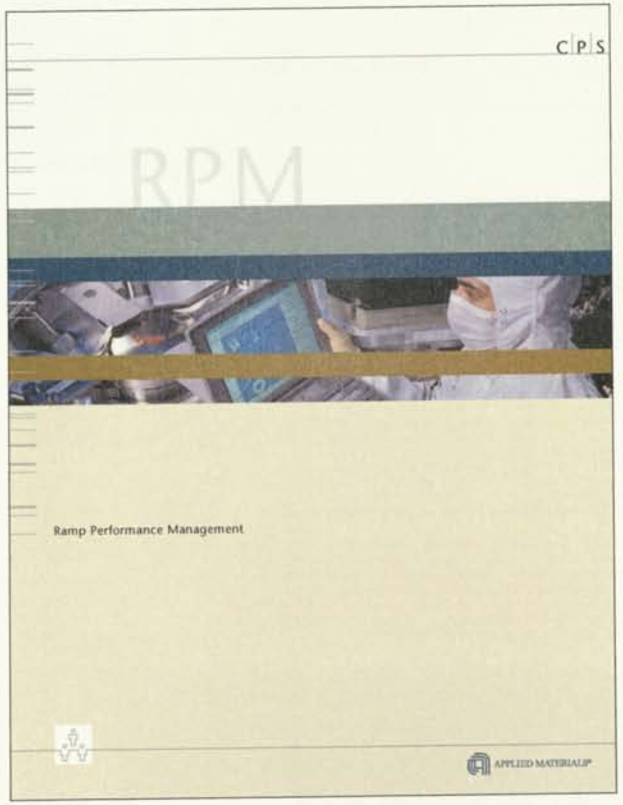


C|P|I

ENDURA XP 300

APPLIED MATERIALS

CPI Division Brochure



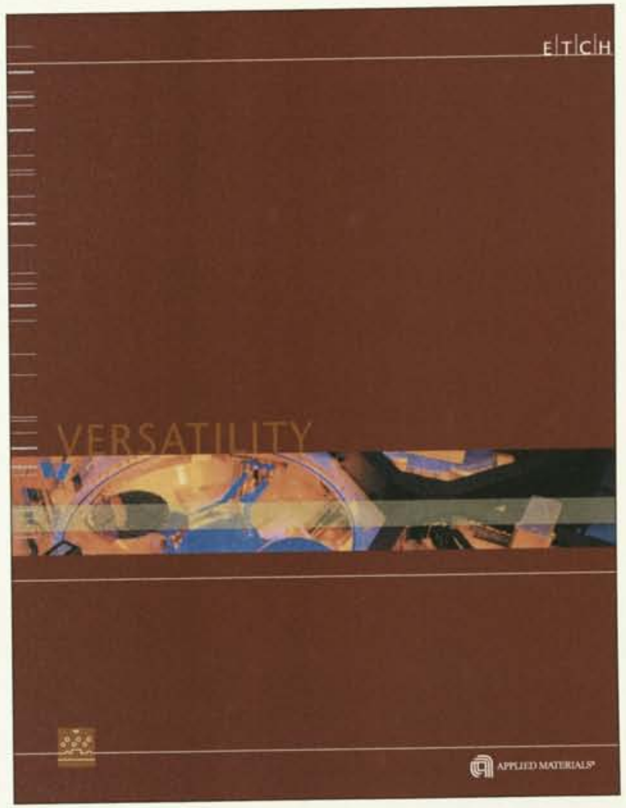
C|P|S

RPM

Ramp Performance Management

APPLIED MATERIALS

CPS Division Brochure

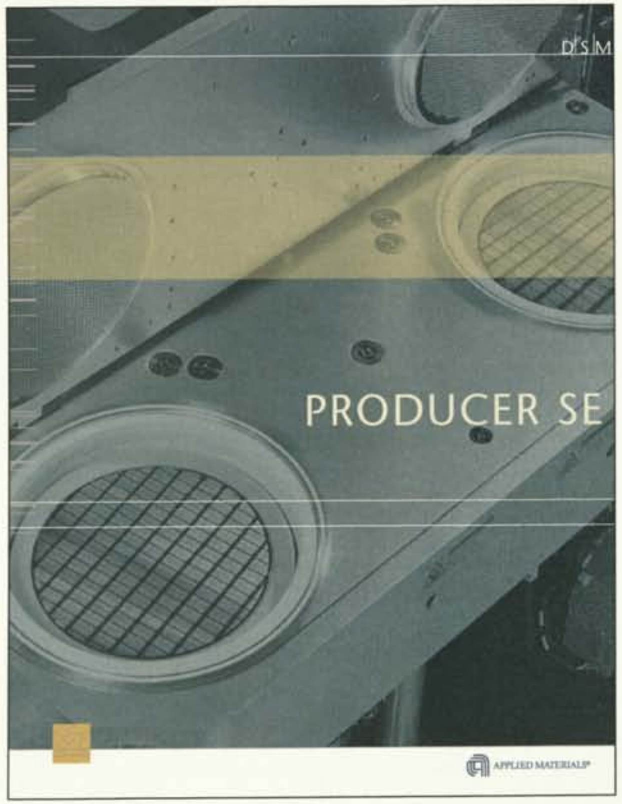


E|T|C|H

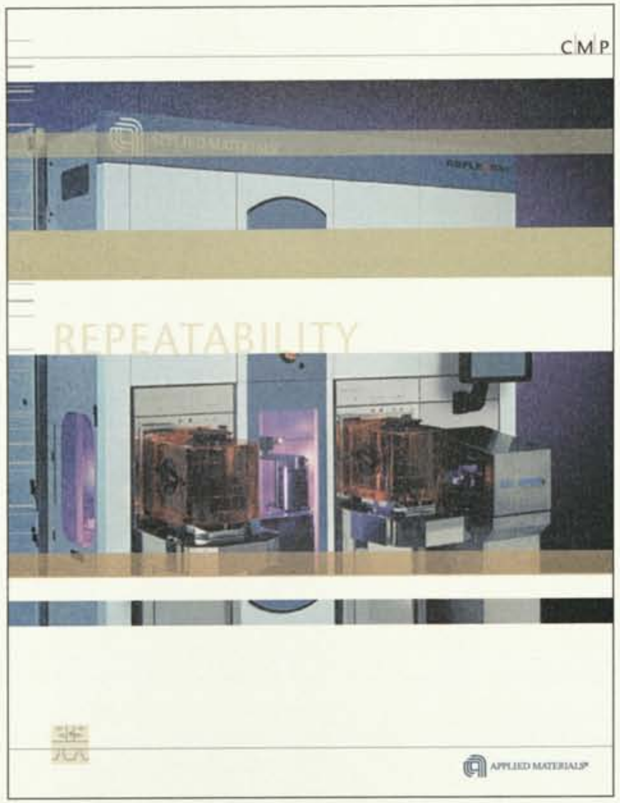
VERSATILITY

APPLIED MATERIALS

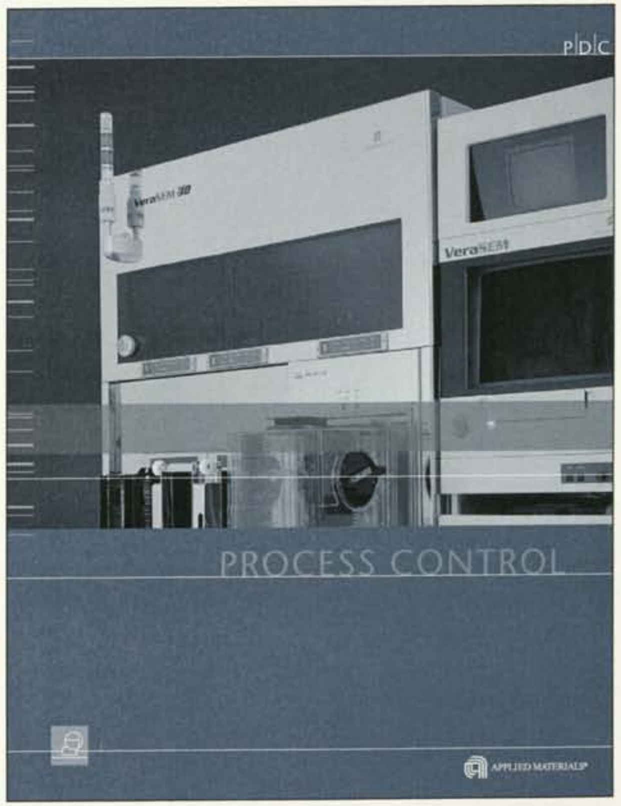
Etch Division Brochure



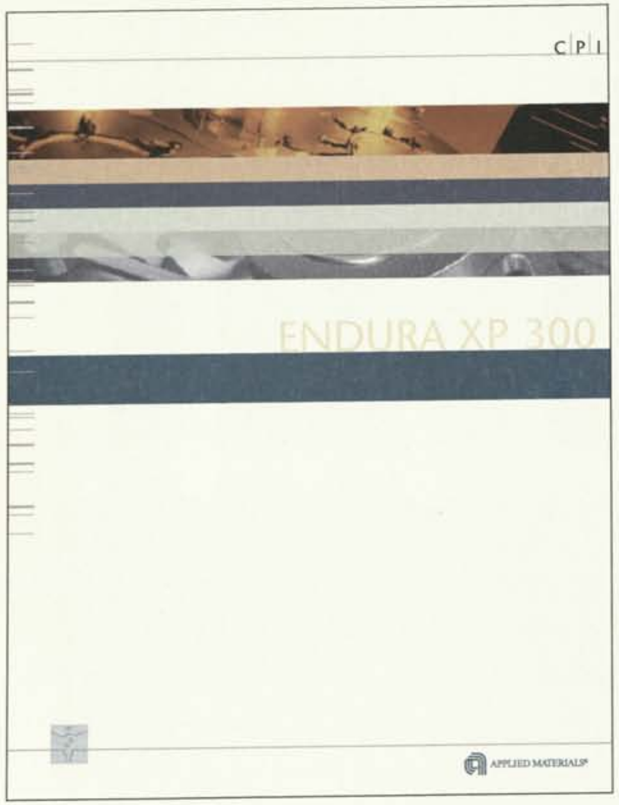
DSM Division Brochure



CMP Division Brochure



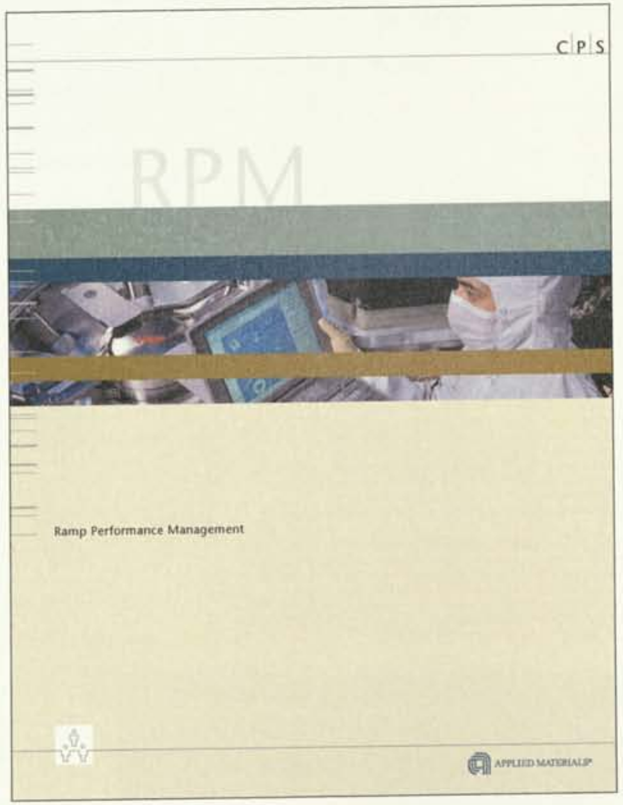
PDC Division Brochure — two-color option


C|P|I

ENDURA XP 300

APPLIED MATERIALS

CPI Division Brochure

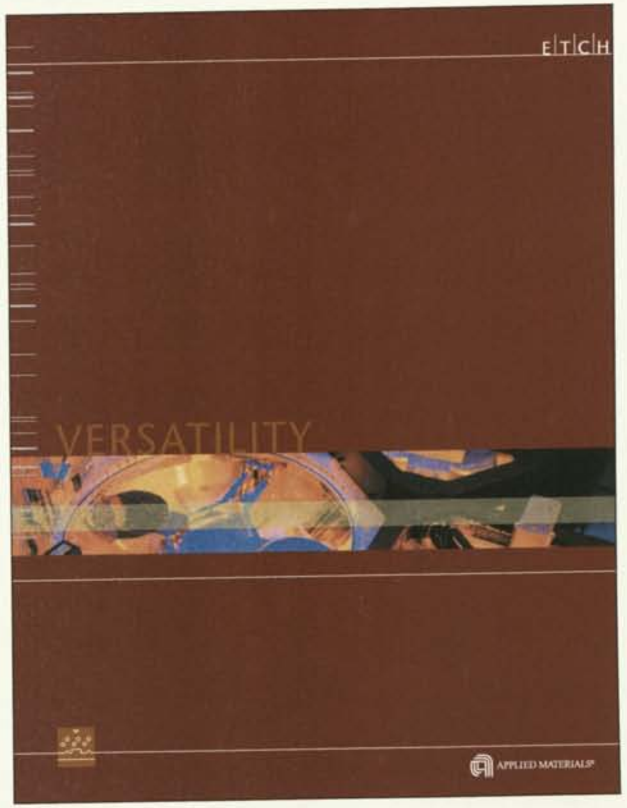

C|P|S

RPM

Ramp Performance Management

APPLIED MATERIALS

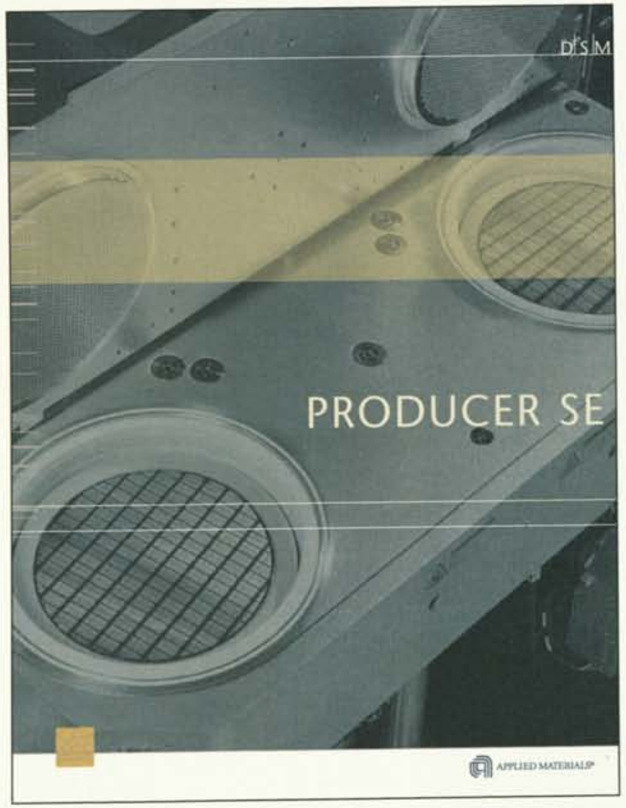
CPS Division Brochure


E|T|C|H

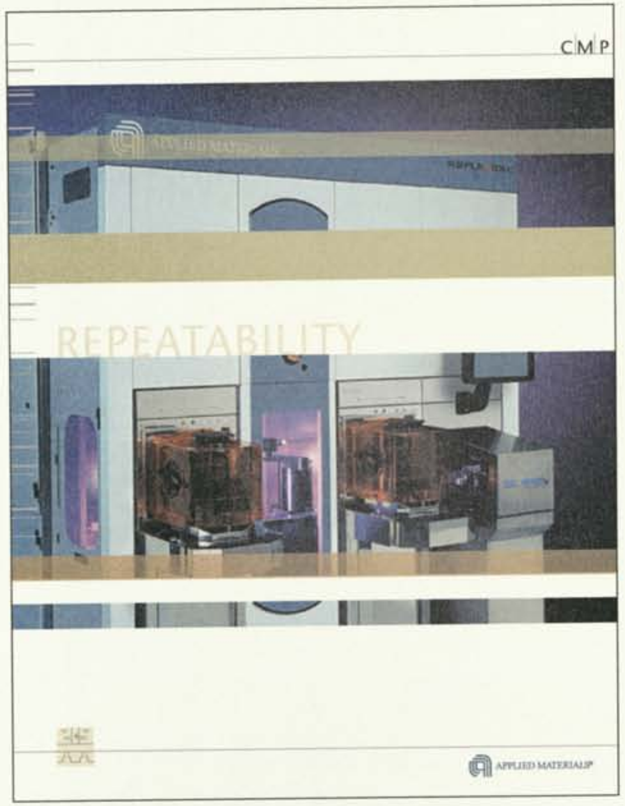
VERSATILITY

APPLIED MATERIALS

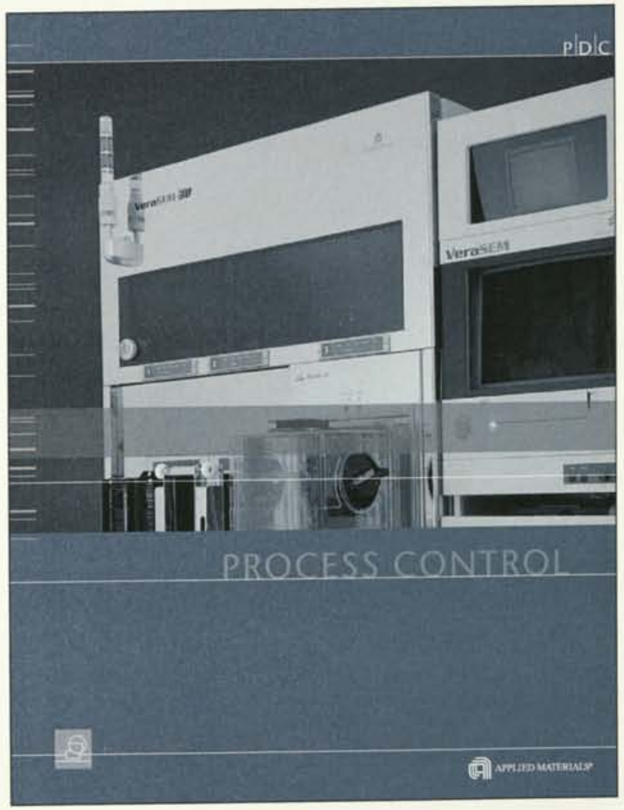
Etch Division Brochure



DSM Division Brochure



CMP Division Brochure



PDC Division Brochure — two-color option

c|p|i

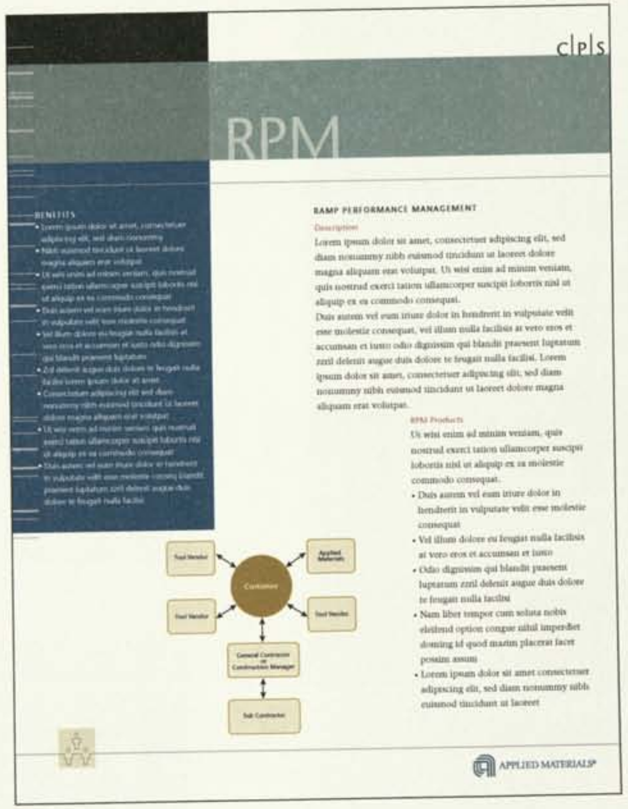
SLAB AND FILL

ADVANCED ALUMINUM SOLUTIONS 200/300mm

Continuing its leadership in Aluminum interconnect (slab) and Aluminum planarization (fill) solutions, Applied Materials has incorporated the latest advances in mainframe technology with the Endura® XP 300 system. Typical 300mm Al interconnect stacks achieve high throughput of >75wph. Al target life has been extended by >50%, and improved target design results in lower COO and COC for Al slab applications. In addition, reliable Al fill capability achieves high aspect ratios (0.25µm) at low temperatures. SIP Ti provides superior sidewall coverage compared to conventional Ti wetting layers and enables Aluminum fill of narrow, high aspect ratio vias (<0.18µm, 3:1) at low temperatures (<400°C).

APPLIED MATERIALS®

CPI Datasheet



c|p|s

RPM

BENEFITS

RAMP PERFORMANCE MANAGEMENT

Description

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Duis autem vel eum iriure dolor in hendrerit in vulputate velit esse molestie consequat, vel illum nulla facilisis at vero eros et accumsan et iusto odio dignissim qui blandit praesent luptatum zzril delenit augue duis dolore te feugait nulla facilisi. Lorem ipsum dolor sit amet, consectetuer adipiscing elit, sed diam nonummy nibh euismod tincidunt ut laoreet dolore magna aliquam erat volutpat.

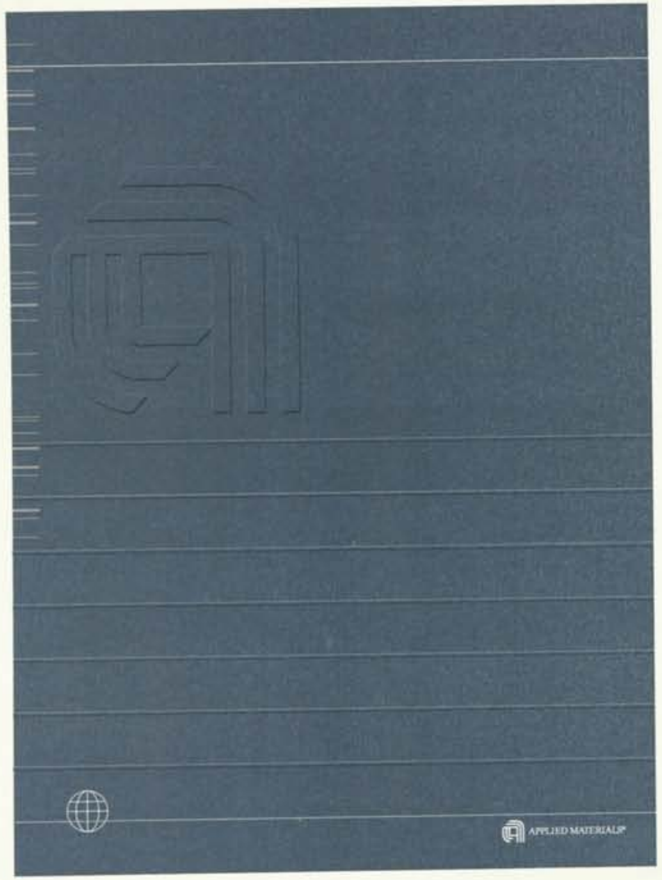
RPM Products

Ut wisi enim ad minim veniam, quis nostrud exerci tation ullamcorper suscipit lobortis nisl ut aliquip ex ea molestie commodo consequat.

- Duis autem vel eum iriure dolor in hendrerit in vulputate velit esse molestie consequat
- Vel illum dolore eu feugiat nulla facilisis at vero eros et accumsan et iusto
- Odio dignissim qui blandit praesent luptatum zzril delenit augue duis dolore te feugait nulla facilisi
- Nam liber tempor cum soluta nobis eleifend option congue nihil imperdiet doming id quod mazim placerat facer possim assum
- Lorem ipsum dolor sit amet consectetuer adipiscing elit, sed diam nonummy nibh euismod tincidunt ut laoreet

APPLIED MATERIALS®

CPS Datasheet



Corporate Folder – embossed logo and lines

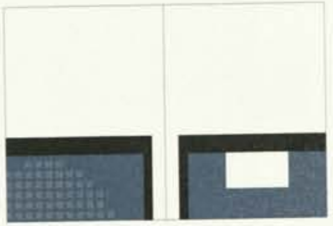
Corporate Folder Interior

TECHNICAL/WAFER

The Creative:

Corporate Brochure

Corporate Folder



Product Brochure Covers

CPI Datasheet

The Concept:

TECHNICAL/WAFER.

The circular graphic represents a wafer in which the division icons are set. By doing this, comparison is made between the cooperative units of Applied Materials and the many components of a completed chip.

Core Values:

Applied Materials is the largest supplier of products and services to the global semiconductor industry and is one of the world's leading information infrastructure providers. Applied Materials enables Information for Everyone by helping semiconductor manufacturers produce more powerful, portable and affordable chips.

Target Audience:

Varies on the collateral pieces. Materials generally target the CIO, CFO or the technology decision makers within a chip making organization.

Primary Objective:

To create a recognizable, unique brand identity that is consistent in messaging and design.
The Look and Feel needs to express Applied Materials' personality and position in a global marketplace.

Survey Results:

(a brief summary)

- To become more **approachable**
- **Less autonomy** among divisions
- Create **brand recognition**
- Continue to project **leadership** image
- **Humanizing** technical aspects of literature
- **Less conservative** image
- Moving towards a **brighter future**

APPLIED MATERIALS BASICS

APPLIED MATERIALS STYLE GUIDE

TECHNICAL/WAFER

Typography:

Trade Gothic Light
Trade Gothic Light Oblique
Trade Gothic
Trade Gothic Oblique
Trade Gothic Bold
Trade Gothic Bold Oblique
Trade Gothic Bold 2
Trade Gothic Bold 2 Oblique
Trade Gothic Condensed
Trade Gothic Condensed Oblique

Minion Regular
Minion Regular Italic
Minion Semibold
Minion Semibold Italic
Minion Black

Color Palette:

Corporate

🟦	🟥	🟫
PMS 5405	PMS 1795	PMS 874

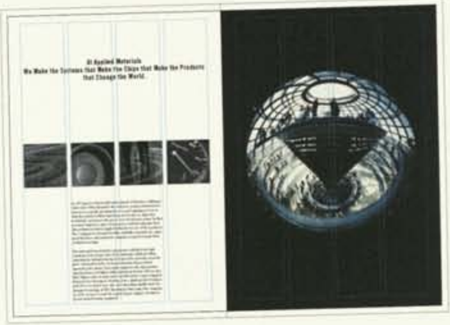
primary	CPI	DSM	ECH	CMP	TCG	PCI	FPS	CPS	PDC	MSK	FPD
	PMS 144	PMS 173	PMS 216	PMS 470	PMS 259	PMS 5405	PMS 5767	PMS 5545	PMS 5487	PMS 647	PMS 668

Division Icon System:

Cu, PVD and Integrated Systems and Modules
Dielectric Systems and Modules
Etch
Chemical Mechanical Polishing
Transitor and Capacitor
Parametric and Conductive Implant
Factory Productivity Solutions
Customer Productivity Support
Process Diagnostics and Control
Mask Business Sector
Display Business Sector

The Grid System:

The basic Grid System is a 4 column grid. There are some consistency of the graphics such as the logo, the border, the icon.

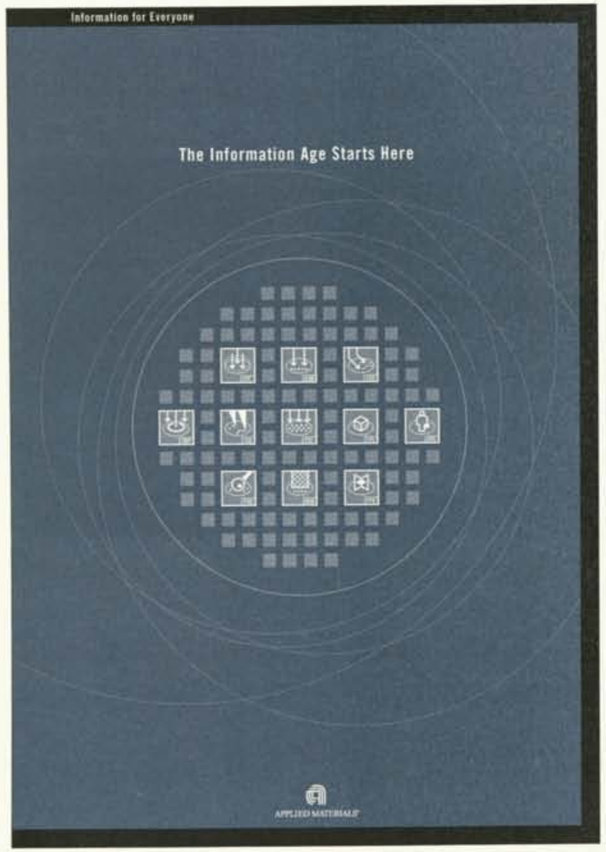


Treatment of the Photography:

Color photograph is used for product.

Black & white photograph is used for metaphor and people.

elevenei**ghty**five**design**

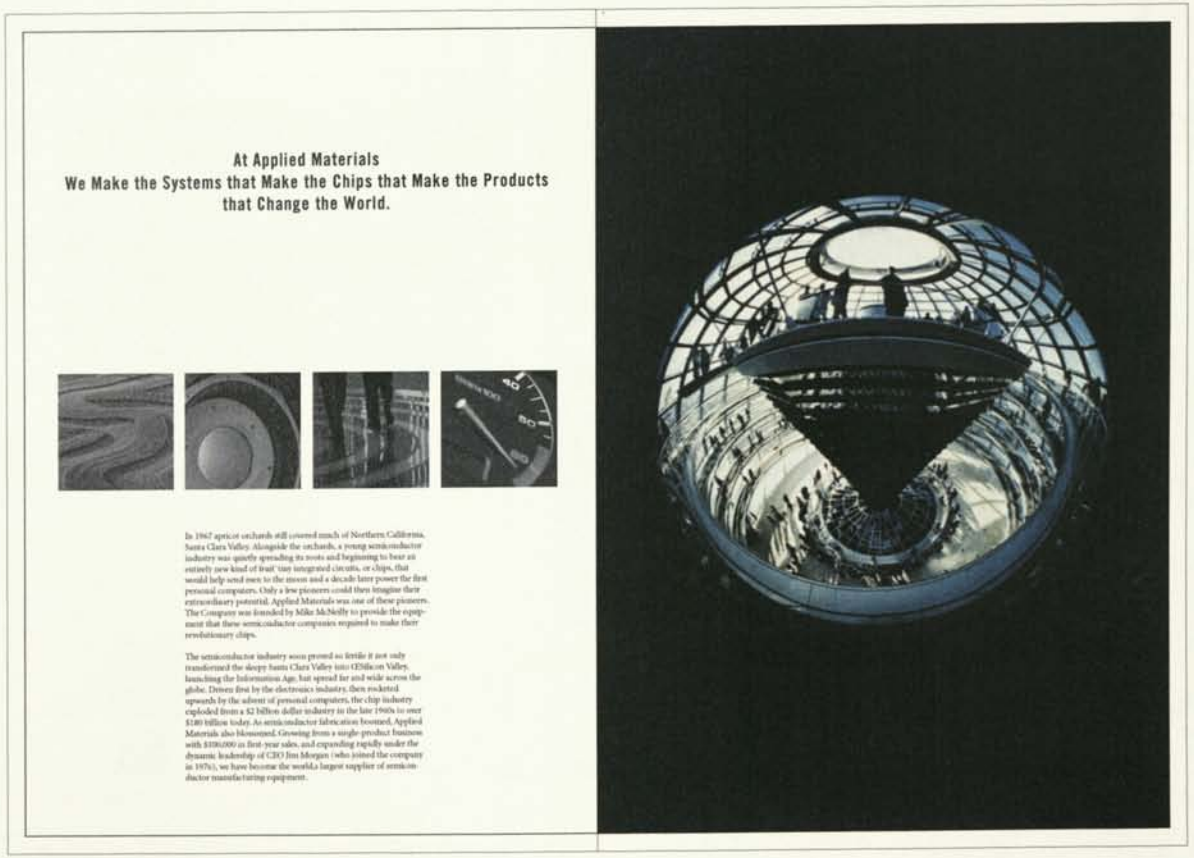


Information for Everyone

The Information Age Starts Here

APPLIED MATERIALS

Corporate Brochure (cover)



At Applied Materials
We Make the Systems that Make the Chips that Make the Products
that Change the World.

In 1967 apricot orchards still covered much of Northern California. Santa Clara Valley. Alongside the orchards, a young semiconductor industry was quietly spreading its roots and beginning to bear an entirely new kind of fruit: tiny integrated circuits, or chips, that would help send men to the moon and a decade later power the first personal computers. Only a few pioneers could then imagine their extraordinary potential. Applied Materials was one of these pioneers. The Company was founded by Mike McNeilly to provide the equipment that these semiconductor companies required to make their revolutionary chips.

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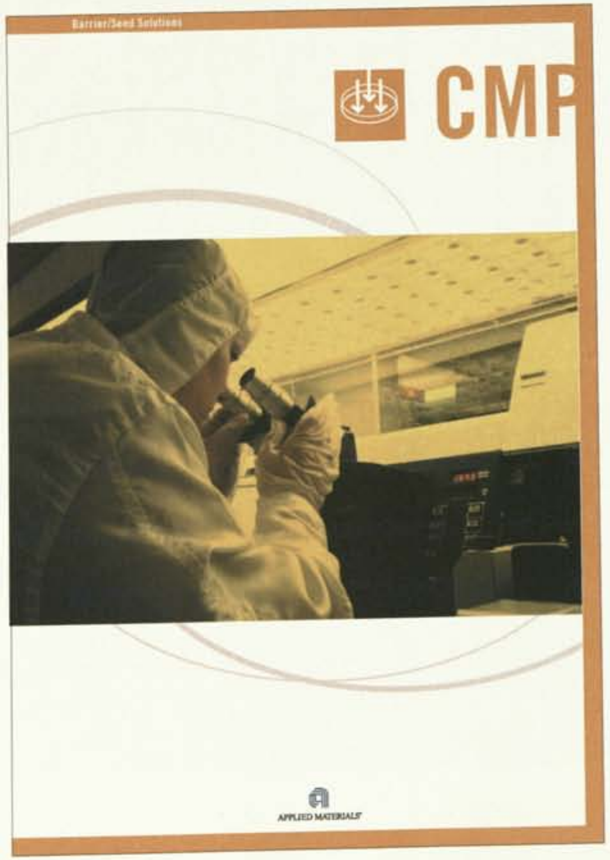
Corporate Brochure (spread)



CMP Brochure (cover)

CPS Brochure (cover)

Al Slab and Fill Solutions

Endura

CMP

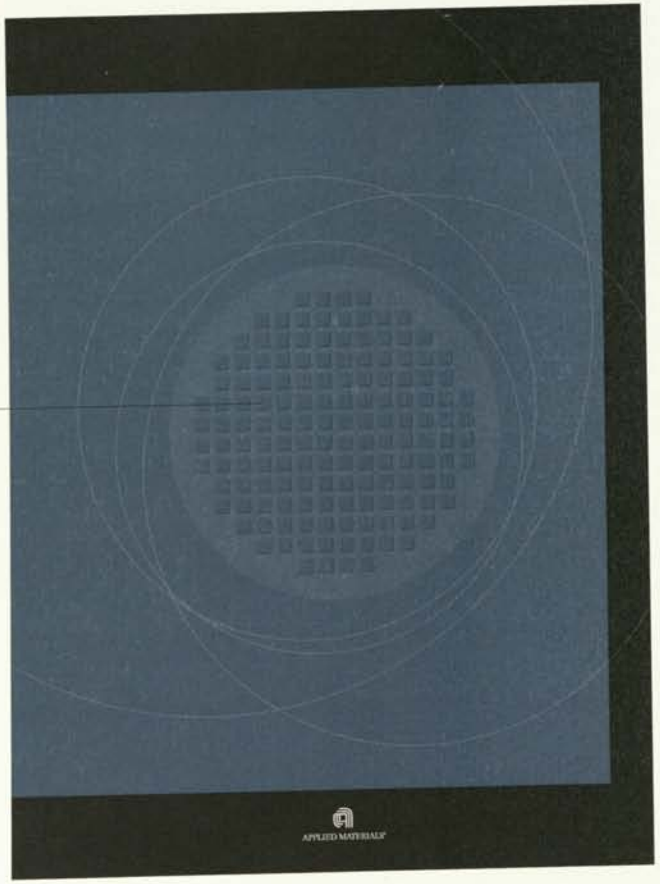
ADVANCED ALUMINUM SOLUTIONS 200/300mm

Continuing its leadership in Aluminum interconnect (slab) and Aluminum planarization (fill) solutions, Applied Materials has incorporated the latest advances in mainframe technology with the Endura® XP 300 system.

Typical 300mm Al interconnect stacks achieve high throughput of >75wph. Al target life has been extended by >50%, and improved target design results in lower COO and COC for Al slab applications. In addition, reliable Al fill capability achieves high aspect ratios (0.25µm) at low temperatures. SIP Ti provides superior sidewall coverage compared to conventional Ti wetting layers and enables Aluminum fill of narrow, high aspect ratio vias (<0.18µm, 5:1) at low temperatures (<400°C).

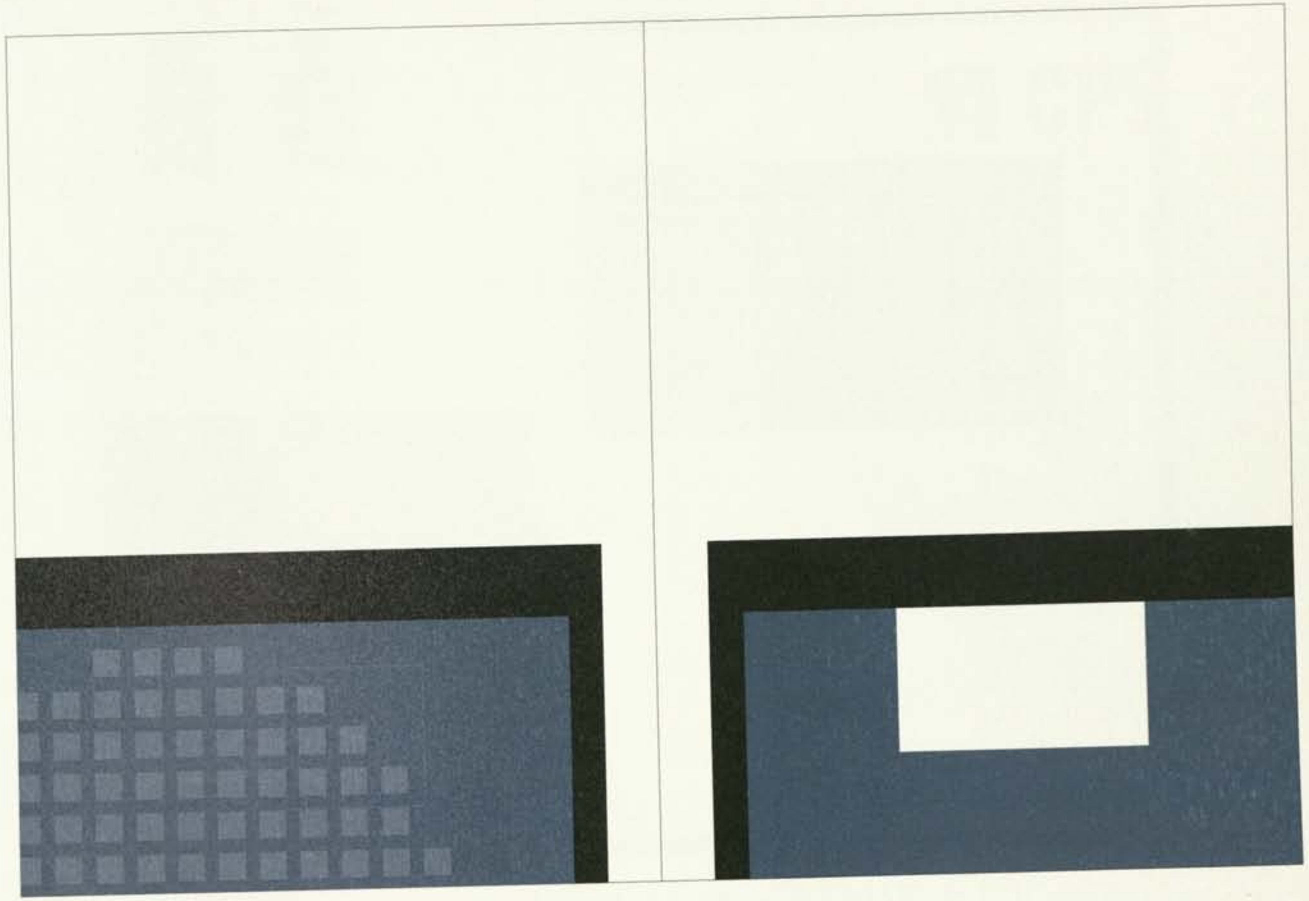
APPLIED MATERIALS®

CMP Data Sheet



squares embossed

Corporate Folder (outside)



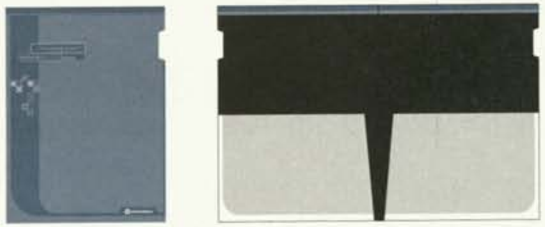
Corporate Folder (inside)

ONE BRAND

eleveneightyfivedesign

The Creative:

Corporate Brochure



Corporate Folder

CPI Data sheet

Product Brochure Covers

The Concept: One Brand

This system pulls from the one constant for the past 20 years of Applied Materials, the corporate logo. In the ever-changing and dynamic market of chip manufacturing, Applied Materials has met the demands of that market and it's identity has stood to represent quality, stability and a leader.

The graphical elements in this system are designed to compliment the logo. The curved corners are derivative of the Applied Materials logo. The beveled notch is derivative of the patterns on a chip.

The icons are constructed utilizing two shapes; the square (representing a chip) and the circle (representing the wafer) and are used as patterns in all eleven divisions. The corporate system incorporates overlapping type as a pattern and allows for key words to be implemented and used in this fashion. Patterns are used in the system to convey the idea that Applied Materials is a fully integrated company in both its products and its customers.

Core Values:

Applied Materials is the largest supplier of products and services to the global semiconductor industry and is one of the world's leading information infrastructure providers. Applied Materials enables Information for Everyone by helping semiconductor manufacturers produce more powerful, portable and affordable chips.

Target Audience:

Varies on the collateral pieces. Materials generally target the CIO, CFO or the technology decision makers within a chip making organization.

Primary Objective:

To create a recognizable, unique brand identity that is consistent in messaging and design. The Look and Feel needs to express AMAT's personality and position in a global marketplace.

Survey Results:

(a brief summary)

- To become more **approachable**
- **Less autonomy** among divisions
- Create **brand recognition**
- Continue to project **leadership** image
- **Less conservative** image
- Moving towards a **brighter future**

APPLIED MATERIALS STYLE GUIDE

ONE BRAND

Typography:

Akzidenz Grotesk Light
Akzidenz Grotesk Roman
Akzidenz Grotesk Bold
Akzidenz Grotesk Black

Adobe Caslon Regular
Adobe Caslon Italic
Adobe Caslon SemiBold
Adobe Caslon SemiBold Italic
Adobe Caslon Bold
Adobe Caslon Bold Italic

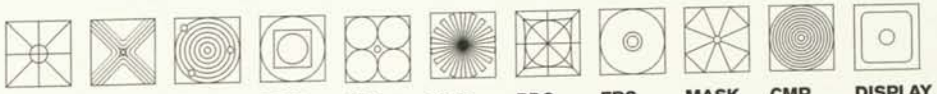
Color Palette:

Corporate

PMS 5405	PMS 1795	PMS 143	C. Gray 2	C. Gray 5	PMS 425	PMS 5483	PMS 5743	PMS 4515

CPI	DSM	ECH	CMP	TCG	PCI	FPS	CPS	PDC	MSK	FPD
PMS 153	PMS 5497	PMS 539	PMS 533	PMS 174	PMS 5473	PMS 4525	PMS 371	PMS 458	PMS 5115	PMS 422
PMS 877 METALLIC	PMS 875 METALLIC	PMS 5425	PMS 8380 METALLIC	W. GRAY 6	PMS 8240 METALLIC	PMS 1815	PMS 465	PMS 418	PMS 550	PMS 5477

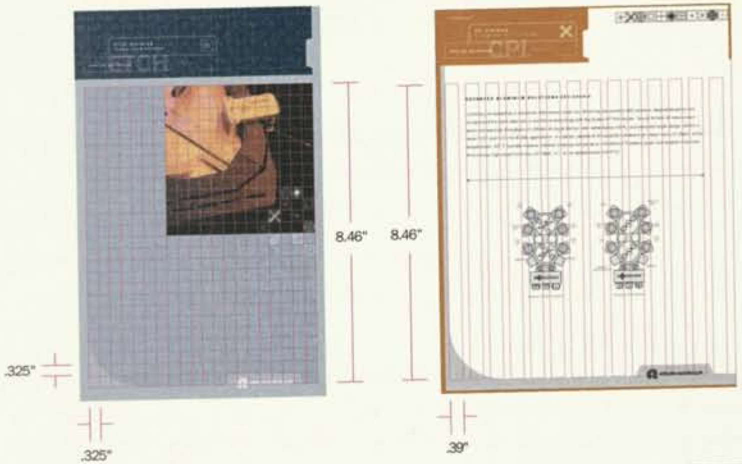
Division Identifiers, Acronyms and Icons:



ETCH precision and alignment
CPI conductive material & electrical current
PCI ion implantation
DSM non-conductive layer, insulation
CPS customer service
TCG radiating of heat
PDC measure depth & defects, inspect
FPS management software
MASK negative area, light coming through
CMP polishing
DISPLAY monitor

The Grid System:

The basic Grid System is dividing the page into 20x26 squares which is used for positioning of elements within the page. There is also a 14 column grid, for text that fits into the Square grid system, any combination of the column grid is acceptable except a one column usage.



Consistent Elements:

The logo is always placed in the same area (lower right)

The curve is always placed in the same area (lower left)

The colored block with pattern always butts to the upper left corner

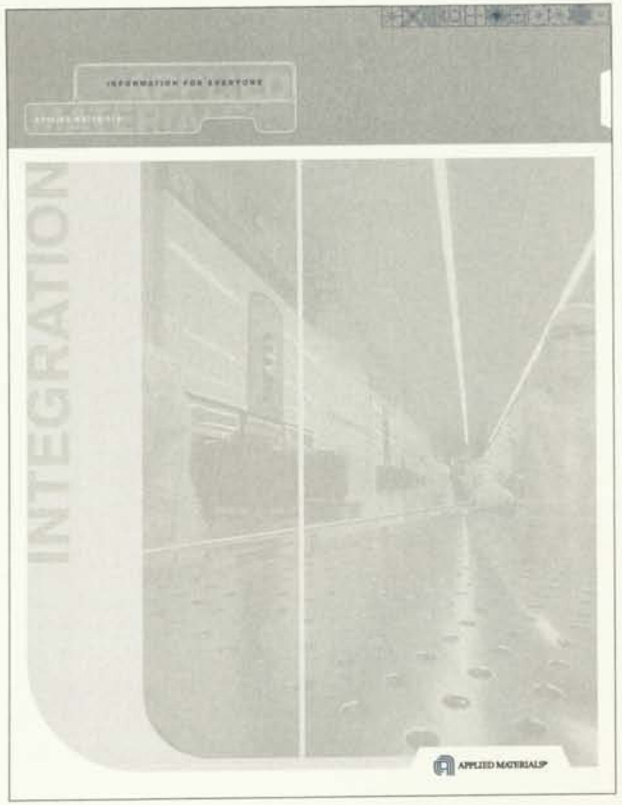
Treatment of the Photography:

Corporate covers should use imagery as a subtle duotone of a corporate color used within the space shown below. Corporate materials can utilize either full color imagery or black and white imagery in the interior spreads and has the flexibility within the collateral to bleed images or contain images in boxes or shapes that relate to the look and feel.

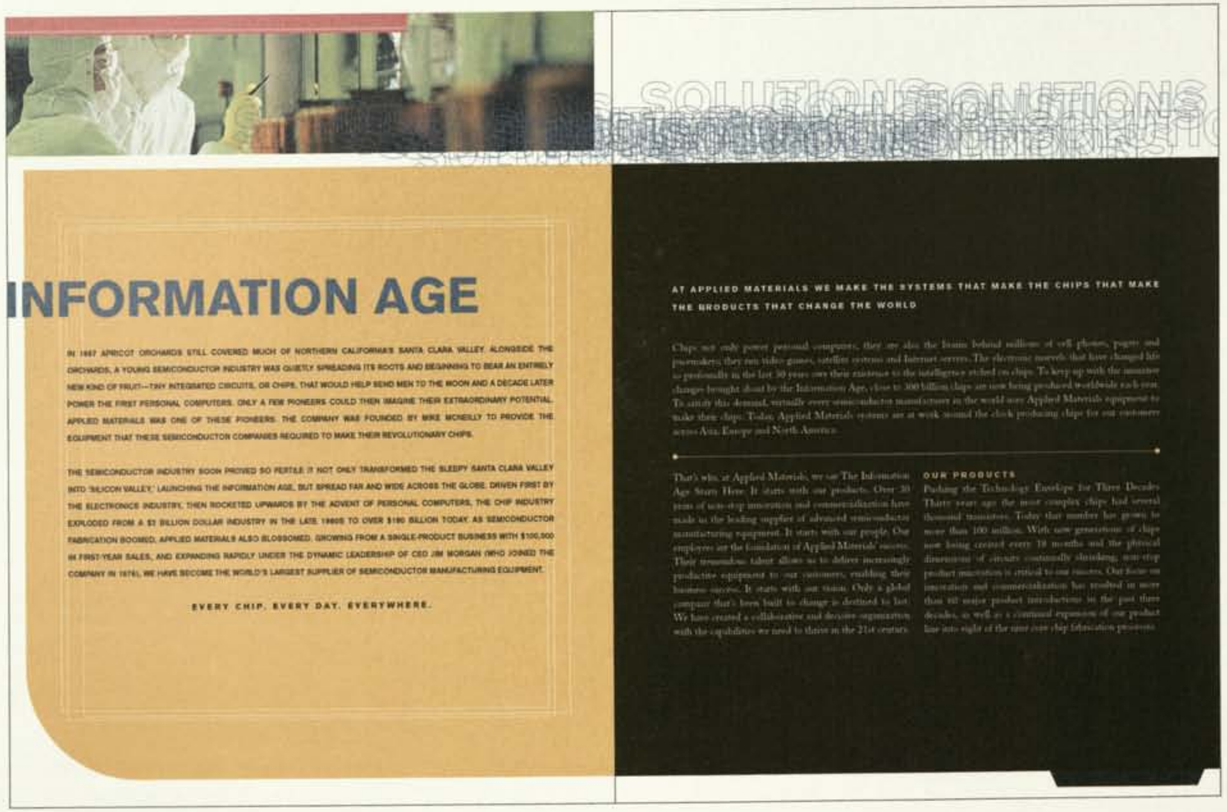
Corporate Usage:
Image should be placed within this space

Images should be cropped in tightly and used within a square format

Division materials may use images in either full color or in black and white, but must remain in a square that is created by the underlying grid. The square size can vary and the image must interact and touch with the line art. Images can bleed within the space, but should be in a subtle duotone if used in this way. Images should also be cropped in an interesting way.



Corporate Brochure Cover



INFORMATION AGE

IN 1967 APRICOT ORCHARDS STILL COVERED MUCH OF NORTHERN CALIFORNIA'S SANTA CLARA VALLEY. ALONGSIDE THE ORCHARDS, A YOUNG SEMICONDUCTOR INDUSTRY WAS QUIETLY SPREADING ITS ROOTS AND BEGINNING TO BEAR AN ENTIRELY NEW KIND OF FRUIT—TINY INTEGRATED CIRCUITS, OR CHIPS, THAT WOULD HELP SEND MEN TO THE MOON AND A DECADE LATER POWER THE FIRST PERSONAL COMPUTERS. ONLY A FEW PIONEERS COULD THEN IMAGINE THEIR EXTRAORDINARY POTENTIAL. APPLIED MATERIALS WAS ONE OF THESE PIONEERS. THE COMPANY WAS FOUNDED BY MIKE MCNEILLY TO PROVIDE THE EQUIPMENT THAT THESE SEMICONDUCTON COMPANIES REQUIRED TO MAKE THEIR REVOLUTIONARY CHIPS.

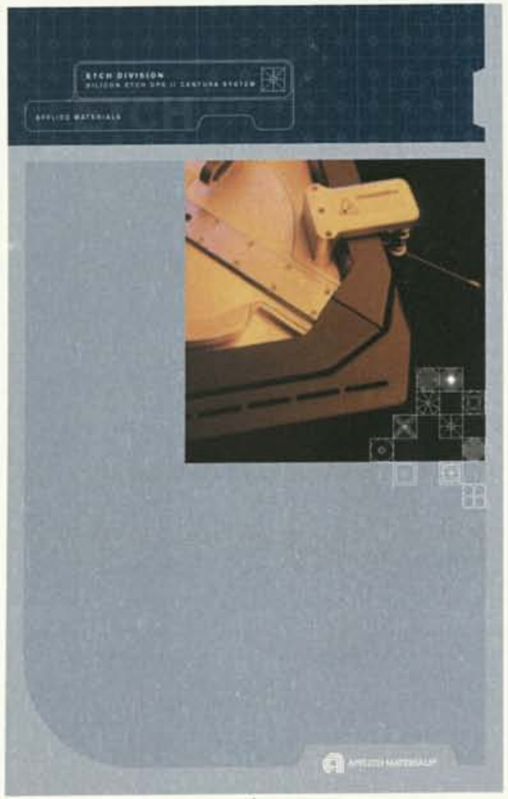
THE SEMICONDUCTOR INDUSTRY SOON PROVED SO FERTILE IT NOT ONLY TRANSFORMED THE SLEEPY SANTA CLARA VALLEY INTO "SILICON VALLEY," LAUNCHING THE INFORMATION AGE, BUT SPREAD FAR AND WIDE ACROSS THE GLOBE. DRIVEN FIRST BY THE ELECTRONICS INDUSTRY, THEN ROCKETED UPWARDS BY THE ADVENT OF PERSONAL COMPUTERS, THE CHIP INDUSTRY EXPLODED FROM A $2 BILLION DOLLAR INDUSTRY IN THE LATE 1960S TO OVER $150 BILLION TODAY. AS SEMICONDUCTOR FABRICATION BOOMED, APPLIED MATERIALS ALSO BLOSSOMED. GROWING FROM A SINGLE-PRODUCT BUSINESS WITH $100,000 IN FIRST-YEAR SALES, AND EXPANDING RAPIDLY UNDER THE DYNAMIC LEADERSHIP OF CEO JIM MORGAN (WHO JOINED THE COMPANY IN 1976), WE HAVE BECOME THE WORLD'S LARGEST SUPPLIER OF SEMICONDUCTOR MANUFACTURING EQUIPMENT.

EVERY CHIP. EVERY DAY. EVERYWHERE.

AT APPLIED MATERIALS WE MAKE THE SYSTEMS THAT MAKE THE CHIPS THAT MAKE THE PRODUCTS THAT CHANGE THE WORLD

OUR PRODUCTS

Corporate Brochure Spread

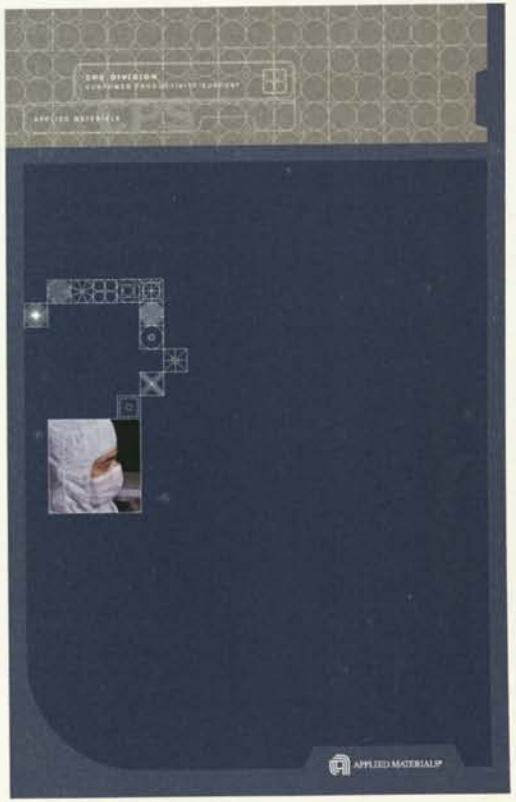


Product Brochure Cover (ETCH)

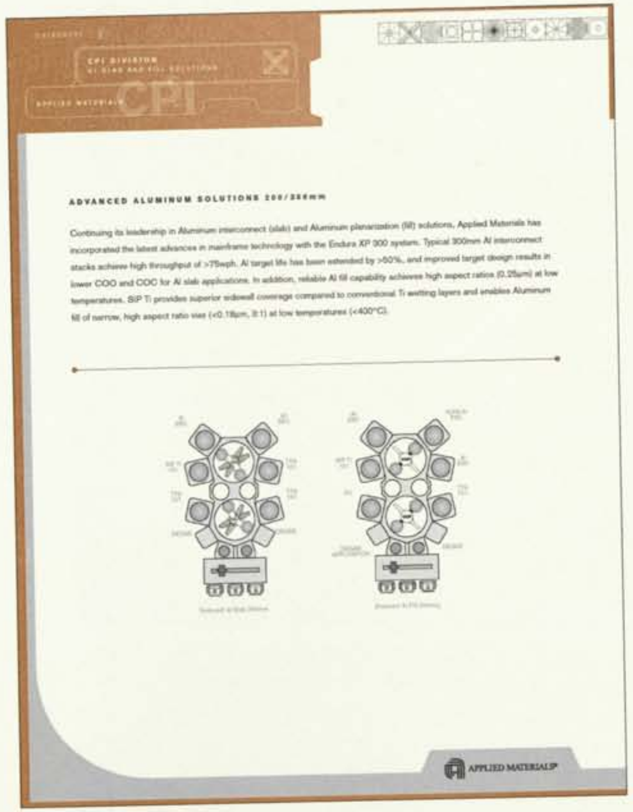
PMS 877 metallic

Product Brochure Cover (CPI)

PMS 8380 metallic



Product Brochure Cover (CPS)



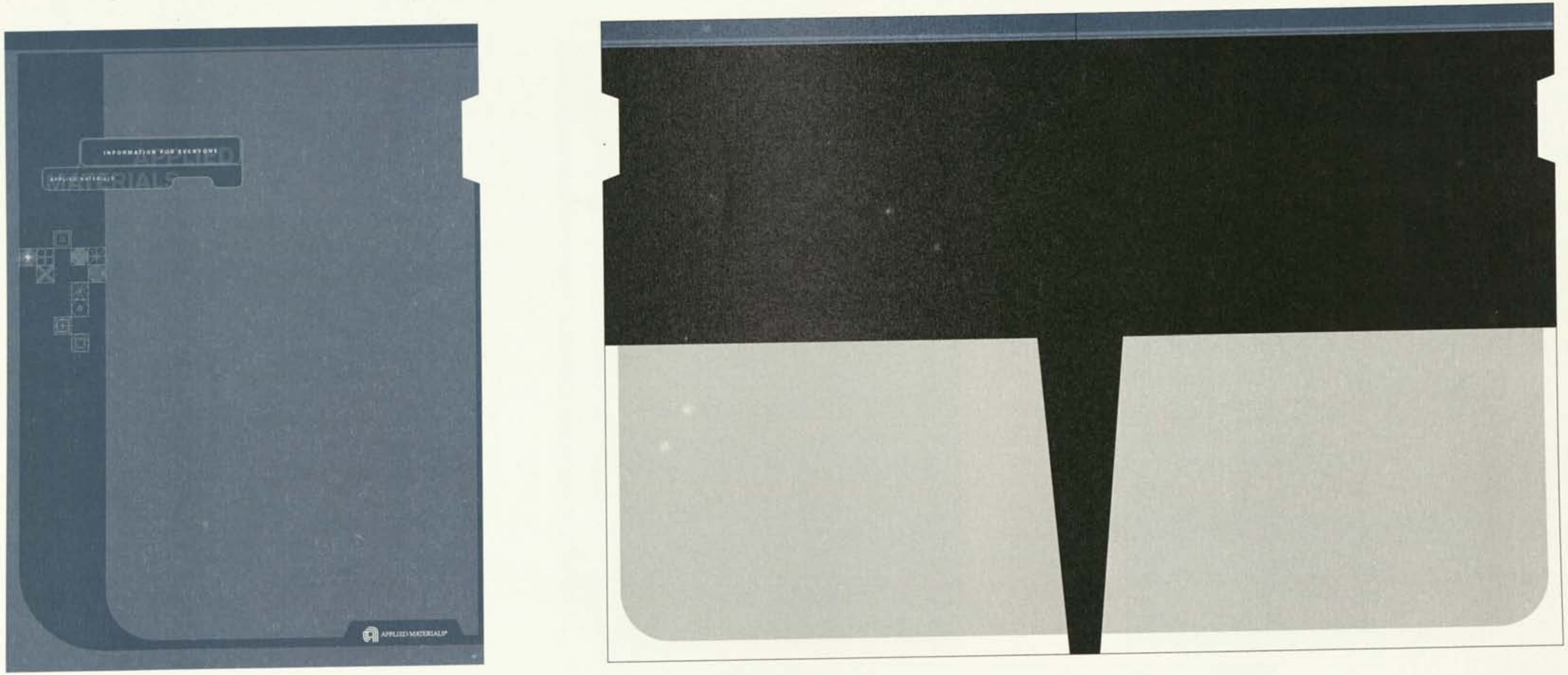
CPI DIVISION
Al SLAB AND FILL SOLUTIONS
APPLIED MATERIALS
CPI

ADVANCED ALUMINUM SOLUTIONS 200/300mm

Continuing its leadership in Aluminum interconnect (slab) and Aluminum planarization (fill) solutions, Applied Materials has incorporated the latest advances in mainframe technology with the Endura XP 300 system. Typical 300mm Al interconnect stacks achieve high throughput of >75wph. Al target life has been extended by >50%, and improved target design results in lower COO and COC for Al slab applications. In addition, reliable Al fill capability achieves high aspect ratios (0.25µm) at low temperatures. SIP Ti provides superior sidewall coverage compared to conventional Ti wetting layers and enables Aluminum fill of narrow, high aspect ratio vias (<0.18µm, 3:1) at low temperatures (<400°C).

APPLIED MATERIALS

CPI Datasheet



Corporate Folder

eleven**eighty**five**design**